

## Features...

- High-performance CMOS EEPROM devices based on second-generation Multiple Array Matrix (MAX) architecture
- Complete EPLD family with logic densities ranging from 600 usable (1,200 available) gates to 5,000 usable (10,000 available) gates (see Table 1)
- 5-ns pin-to-pin logic delays with up to 178.6-MHz counter frequencies (including interconnect)
- PCI-compliant -5, -6, -7, -10P, and -12P speed grades
- Programmable flipflops with individual Clear, Preset, Clock, and Clock Enable controls
- Programmable power-saving mode for 50% or greater power reduction in each macrocell
- Configurable expander product-term distribution allowing up to 32 product terms per macrocell
- 44 to 208 pins available in J-lead (PLCC), pin-grid array (PGA), quad flat pack (QFP), and 1-mm thin quad flat pack (TQFP) packages
- Programmable Security Bit for total protection of proprietary designs
- 3.3-V or 5.0-V operation
  - Full 3.3-V EPM7032V
  - 3.3-V or 5.0-V I/O on all devices (except 44-pin devices)

**Table 1. MAX 7000 Device Features**

Feature	EPM7032	EPM7032V	EPM7064	EPM7096	EPM7128E	EPM7160E	EPM7192E	EPM7256E
Available Gates	1,200	1,200	2,500	3,600	5,000	6,400	7,500	10,000
Usable Gates	600	600	1,250	1,800	2,500	3,200	3,750	5,000
Macrocells	32	32	64	96	128	160	192	256
Maximum User I/O	36	36	68	76	100	104	124	164
t <sub>PD</sub> (ns)	5	12	6	6	7.5	7.5	10	10
t <sub>SU</sub> (ns)	4	10	5	5	6	6	7	7
t <sub>FSU</sub> (ns)	-	-	-	-	3	3	3	3
t <sub>CO1</sub> (ns)	3.5	7	4	4	4.5	4.5	5	5
f <sub>CNT</sub> (MHz)	178.6	90.9	151.5	151.5	125	125	100	100

## ...and More Features

- Enhanced features available in MAX 7000E devices, the higher-density members of the MAX 7000 family
  - Six pin- or logic-driven Output Enable signals
  - Two global Clock signals with optional inversion
  - Enhanced interconnect resources for improved routability
  - Fast input setup times provided by a dedicated path from I/O pin to macrocell registers
  - Programmable output slew-rate control
- Software design support featuring Altera's MAX+PLUS II development system on 486- and Pentium-based PCs and Sun SPARCstation, HP 9000 Series 700, and IBM RISC System/6000 workstations
- Additional design entry and simulation support provided by EDIF, Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Data I/O, Exemplar, Intergraph, Mentor Graphics, OrCAD, Synopsys, and Viewlogic
- Programming support with Altera's Master Programming Unit (MPU) and programming hardware from other manufacturers

## General Description

The MAX 7000 family of high-density, high-performance CMOS devices is based on Altera's second-generation MAX architecture. Fabricated with advanced EEPROM-based CMOS technology, the MAX 7000 family provides 600 to 5,000 usable gates, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 178.6 MHz. The -5, -6, -7, -10P, and -12P speed grades comply with the *PCI Local Bus Specification*. See Table 2 for available speed grades.

**Table 2. MAX 7000 Speed Grades**

Device	Speed Grade									
	-5	-6	-7	-10P	-10	12P	-12	-15	-15T	-20
EPM7032	✓ (1)	✓	✓		✓		✓	✓	✓	
EPM7032V							✓	✓		✓
EPM7064		✓ (1)	✓		✓		✓	✓		
EPM7096		✓ (1)	✓		✓		✓	✓		
EPM7128E			✓ (1)	✓	✓		✓	✓		✓
EPM7160E			✓ (1)	✓	✓		✓	✓		✓
EPM7192E				✓ (1)	✓ (1)	✓ (1)	✓	✓		✓
EPM7256E				✓ (1)	✓ (1)	✓ (1)	✓	✓		✓

**Note:**

(1) This information is preliminary. Contact Altera Marketing at (408) 894-7104 for product availability.

The higher-density members of the MAX 7000 family—called MAX 7000E devices—include the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices. (MAX 7000E device names end with the letter E.) These devices have several enhanced features: additional global clocking, additional Output Enable controls, enhanced interconnect resources, fast input registers, and a programmable slew rate.

The MAX 7000 architecture supports 100% TTL emulation and high-density integration of SSI, MSI, and LSI logic functions. It easily integrates multiple programmable logic devices ranging from PALs, GALs, and 22V10s to MACH, pLSI, and FPGA devices. With speed, density, and I/O resources comparable to commonly used masked gate arrays, MAX 7000 devices are also ideal for gate-array prototyping. MAX 7000 devices are available in a wide range of packages, including plastic J-lead chip carrier (PLCC), ceramic pin-grid array (PGA), plastic quad flat pack (PQFP), power quad flat pack (RQFP), and the 1-mm thin quad flat pack (TQFP). See Table 3.

**Table 3. MAX 7000 Maximum User I/O Pins**    *Note (1)*

Device	44-Pin PLCC	44-Pin PQFP	44-Pin TQFP	68-Pin PLCC	84-Pin PLCC	100-Pin PQFP	160-Pin PQFP	160-Pin PGA	192-Pin PGA	208-Pin RQFP
EPM7032	36	36	36							
EPM7032V	36		36							
EPM7064	36		36	52	68	68				
EPM7096				52	64	76				
EPM7128E					68	84	100			
EPM7160E					64	84	104			
EPM7192E							124	124		
EPM7256E							132 (2)		164	164

**Notes:**

- (1) Contact Altera for up-to-date information on available device package options.
- (2) Perform a complete thermal analysis before committing a design to this device package. See *Operating Requirements for Altera Devices* in this data book for more information.

MAX 7000 devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000 architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and are guaranteed for 100 program and erase cycles.

MAX 7000 devices contain from 32 to 256 macrocells that are combined into groups of 16 macrocells, called Logic Array Blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable Clock, Clock Enable, Clear, and Preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms to provide up to 32 product terms per macrocell.

The MAX 7000 family provides programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000E devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000 devices (except 44-pin devices) can be set for either 3.3-V or 5.0-V operation, allowing MAX 7000 devices to be used in mixed-voltage systems.

The MAX 7000 family is supported by Altera's MAX+PLUS II development system, a single, integrated package that offers schematic, text—including the Altera Hardware Description Language (AHDL)—and waveform design entry; compilation and logic synthesis; simulation and timing analysis; and device programming. MAX+PLUS II provides EDIF 2.0.0 and 3.0.0, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and workstation-based EDA tools. MAX+PLUS II runs on 486- and Pentium-based PCs, and Sun SPARCstation, HP 9000 Series 700, and IBM RISC System/6000 workstations.



For more information, go to the *MAX+PLUS II Programmable Logic Development System & Software Data Sheet* in this data book.

## Functional Description

The MAX 7000 architecture includes the following elements:

- Logic Array Blocks
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable Interconnect Array
- I/O control blocks

The MAX 7000 architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (Clock, Clear, and two Output Enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of the EPM7032, EPM7032V, EPM7064, and EPM7096 devices.

Figure 1. Architecture of EPM7032, EPM7032V, EPM7064 & EPM7096 Devices

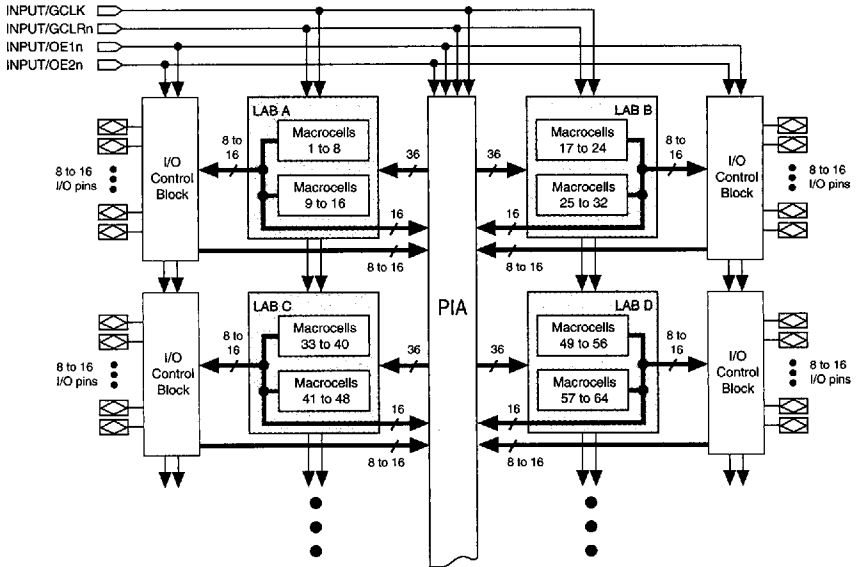
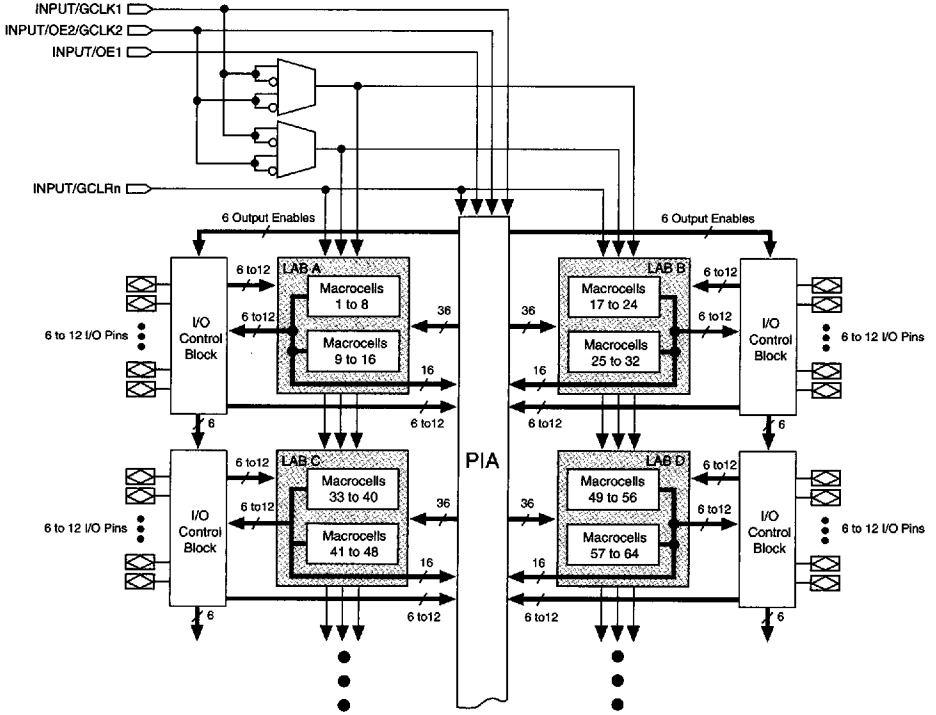


Figure 2 shows the architecture of the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices.

**Figure 2. Architecture of EPM7128E, EPM7160E, EPM7192E & EPM7256E Devices**



### Logic Array Blocks

The MAX 7000 architecture is based on the linking of high-performance, flexible, logic array modules called Logic Array Blocks (LABs). LABs consist of 16-macrocell arrays, as shown in Figures 1 and 2. Multiple LABs are linked together via the Programmable Interconnect Array (PIA), a global bus that is fed by all dedicated inputs, I/O pins, and macrocells.

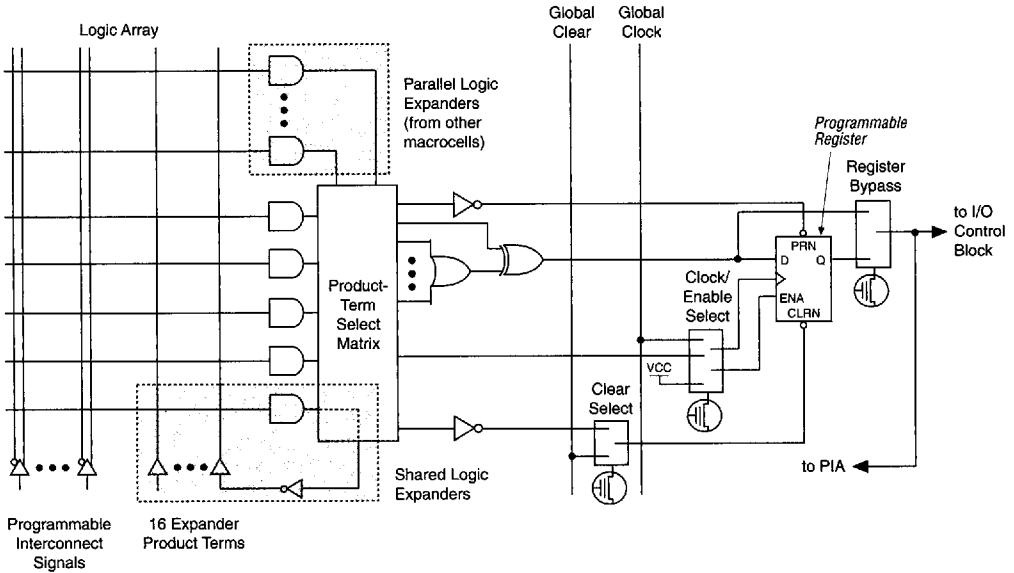
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices

## Macrocells

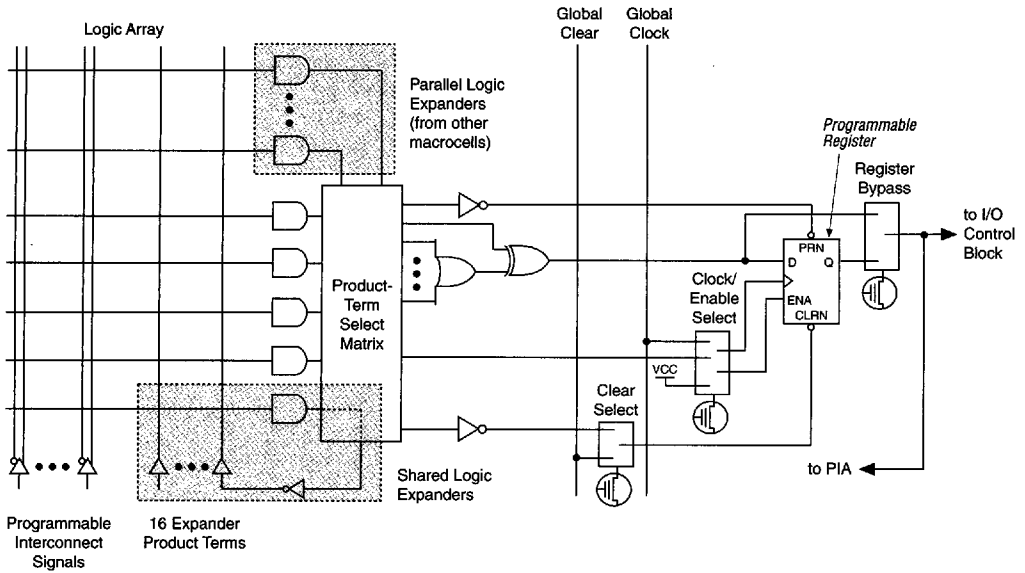
The MAX 7000 macrocell can be individually configured for both sequential and combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7032V, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. Macrocell of EPM7032, EPM7032V, EPM7064 & EPM7096 Devices



The macrocell of EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices is shown in Figure 4.

Figure 4. Macrocell of EPM7128E, EPM7160E, EPM7192E & EPM7256E Devices



Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register Clear, Preset, Clock, and Clock Enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

MAX+PLUS II automatically optimizes product-term allocation according to the logic requirements of the design.

In registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable Clock control. If necessary, the flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; MAX+PLUS II then selects the most efficient flipflop operation for each registered function to optimize resource utilization.



Each programmable register can be clocked in three different modes:

- Clocked by a global Clock signal. This mode achieves the fastest Clock-to-output performance.
- Clocked by a global Clock signal and enabled by an active-high Clock Enable. This mode provides an Enable on each flipflop while still achieving the fast Clock-to-output performance of the global Clock.
- Clocked by an array Clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In the EPM7032, EPM7032V, EPM7064, and EPM7096 devices, the global Clock signal is available from a dedicated Clock pin, *GCLK*, as shown in Figure 1. In the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices, two global Clock signals are available. As shown in Figure 2, these global Clock signals can be the true or the complement of either of the global Clock pins, *GCLK1* or *GCLK2*.

Each register also supports asynchronous Preset and Clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven Preset and Clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register Clear function can be individually driven by the active-low, dedicated, global Clear pin (*GCLRn*).

All MAX 7000E I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast (3-ns) input setup time.

## Expander Product Terms

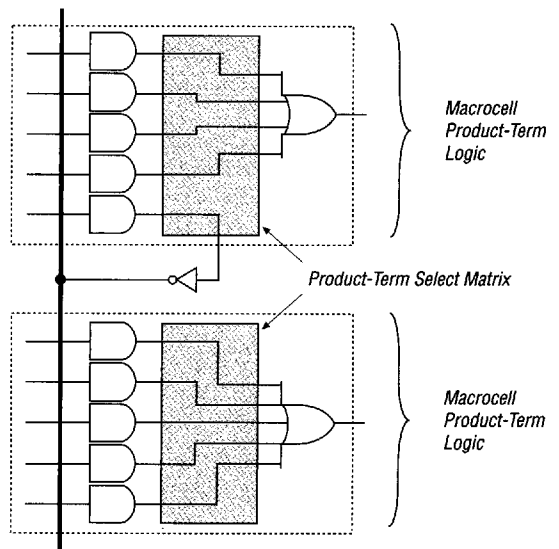
Although most logic functions can be implemented with the five product terms available in each macrocell, some logic functions are more complex and require additional product terms. Another macrocell may be used to supply the required logic resources; however, the MAX 7000 architecture also offers both shareable and parallel expander product terms (“expanders”) that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

### Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay ( $t_{SEXP}$ ) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

**Figure 5. Shareable Expanders**

*Shareable expanders can be shared by any or all macrocells in an LAB.*



### Parallel Expanders

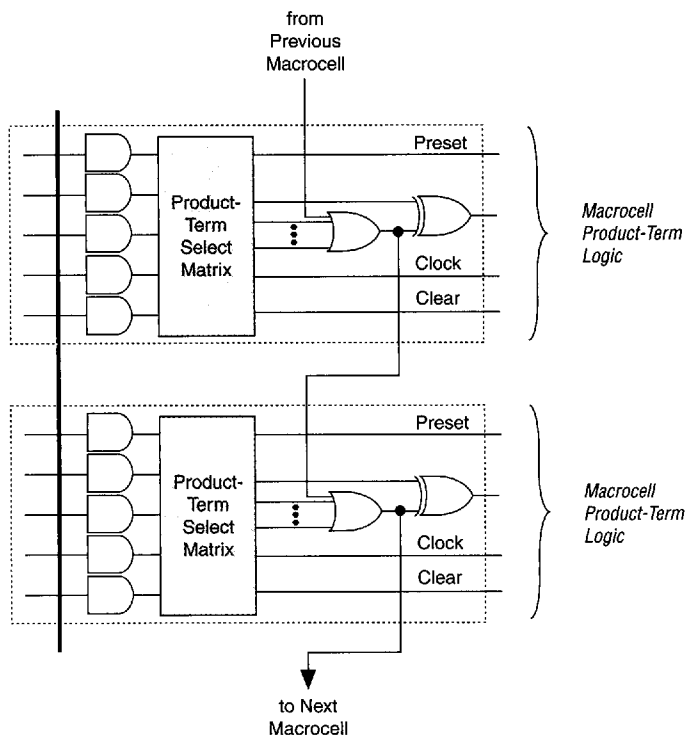
Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with 5 product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

The MAX+PLUS II Compiler can automatically allocate up to 3 sets of up to 5 parallel expanders to the macrocells that require additional product terms. Each set of 5 parallel expanders incurs a small, incremental timing delay ( $t_{PEXP}$ ). For example, if a macrocell requires 14 product terms, the Compiler uses the 5 dedicated product terms within the macrocell and allocates 2 sets of parallel expanders; the first set includes 5 product terms and the second set includes 4 product terms, increasing the total delay by  $2 \times t_{PEXP}$ .

Two groups of 8 macrocells within each LAB (e.g., macrocells 1 to 8 and 9 to 16) form 2 chains to lend or borrow parallel expanders. A macrocell borrows parallel expanders from lower-numbered macrocells. For example, macrocell 8 can borrow parallel expanders from macrocell 7, from macrocells 7 and 6, or from macrocells 7, 6, and 5. Within each group of 8, the lowest-numbered macrocell can only lend parallel expanders and the highest-numbered macrocell can only borrow them. Figure 6 shows how parallel expanders can be borrowed from a neighboring macrocell.

**Figure 6. Parallel Expanders**

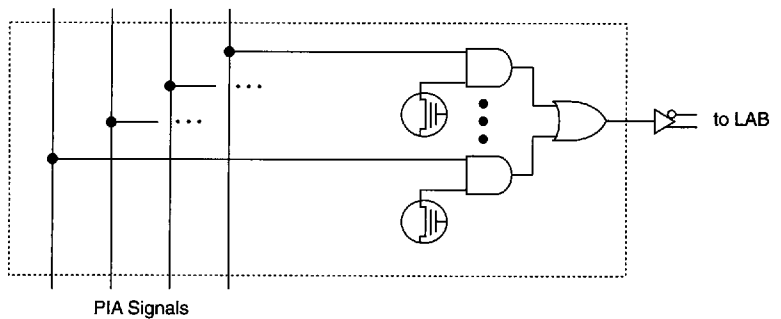
*Unused product terms in a macrocell can be allocated to a neighboring macrocell.*



### Programmable Interconnect Array

Logic is routed between LABs on the Programmable Interconnect Array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes them available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



While the routing delays of channel-based routing schemes in masked or field-programmable gate arrays (FPGAs) are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals, and makes timing performance easy to predict.

## I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global Output Enable signals or directly connected to GND or VCC. Figure 8 shows the I/O control block for the EPM7032, EPM7032V, EPM7064, and EPM7096 devices. The I/O control block has two global Output Enable signals that are driven by two dedicated active-low Output Enable pins (OE1n and OE2n).

**Figure 8. I/O Control Block of EPM7032, EPM7032V, EPM7064 & EPM7096 Devices**

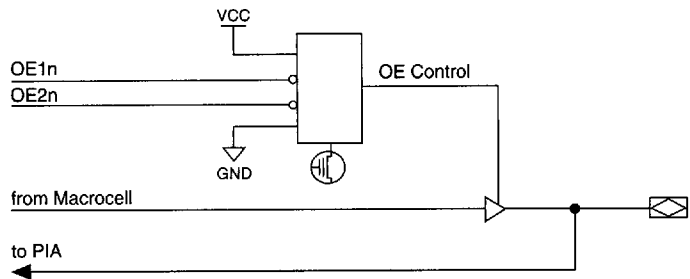
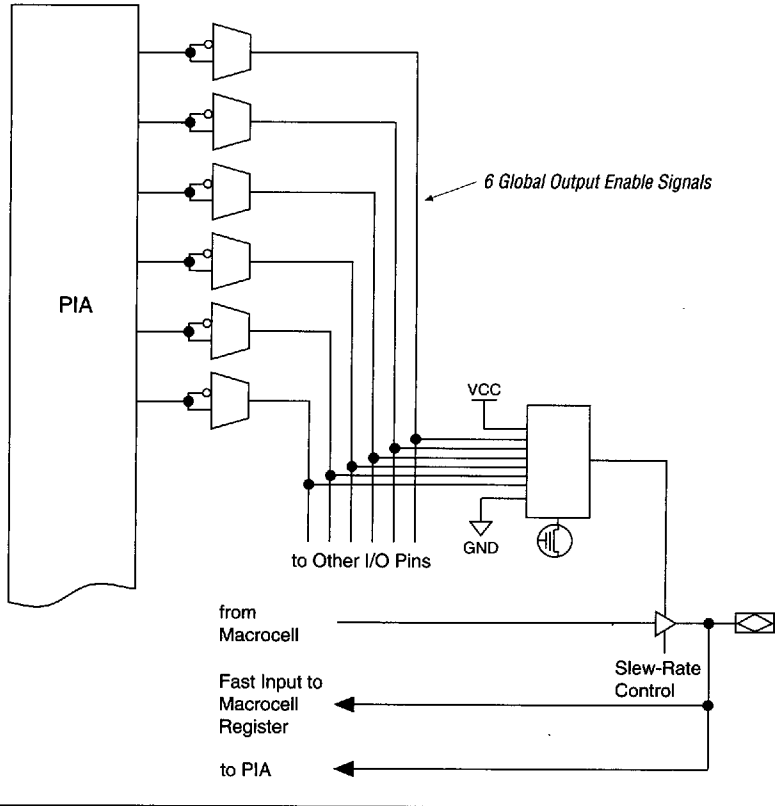


Figure 9 shows the I/O control block of the EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices. The I/O control block has six global Output Enable signals that are driven by the true or complement of two Output Enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.

**Figure 9. I/O Control Block of EPM7128E, EPM7160E, EPM7192E & EPM7256E Devices**



When the tri-state buffer control is connected to GND, the output is tri-stated (high impedance) and the I/O pin can be used as a dedicated input. When the tri-state buffer control is connected to VCC, the output is enabled.

The MAX 7000 architecture provides dual I/O feedback, in which macrocell and pin feedbacks are independent. When an I/O pin is configured as an input, the associated macrocell can be used for buried logic.

## Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, since most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (Turbo Bit on) or low-power (Turbo Bit off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder ( $t_{LPA}$ ) for the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters.

## Slew-Rate Control

The output buffer for each MAX 7000E I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. The slew rate is set to fast when the Turbo Bit is on. A faster slew rate provides very-high-speed transitions, but these fast transitions may introduce more noise transients into the system than a slow slew rate. The fast setting should only be used in speed-critical outputs in systems that are adequately protected against noise. When the Turbo Bit is off, the slew rate is set for low-noise performance, which reduces noise generation and ground bounce.

## 3.3-V or 5.0-V I/O Operation

All MAX 7000 devices, except 44-pin devices, can be set for 3.3-V or 5.0-V I/O operation. These devices have two sets of  $V_{CC}$  pins: one for internal operation and input buffers ( $V_{CCINT}$ ) and another for I/O output drivers ( $V_{CCIO}$ ).

$V_{CCINT}$  pins must always be connected to a 5.0-V power supply. With this  $V_{CCINT}$  level, input voltages are at TTL levels, and are compatible with both 3.3-V and 5.0-V inputs.  $V_{CCIO}$  pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When  $V_{CCIO}$  pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems, and when they are connected to a 3.3-V supply, the output high is 3.3 V and is compatible with 3.3-V systems. Devices operating with  $V_{CCIO}$  levels lower than 4.75 V incur a nominal timing delay adder of the output buffer timing parameter ( $t_{OD}$ ).

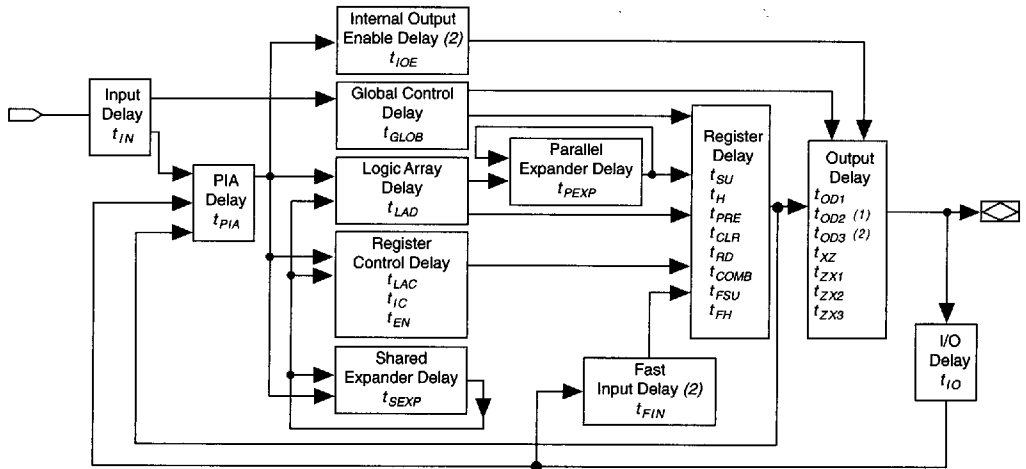
## Design Security

All MAX 7000 devices contain a programmable Security Bit that controls access to the data programmed into the device. When this bit is programmed, a proprietary design implemented in the device cannot be copied or retrieved. This feature provides a high level of design security, since programmed data within EEPROM cells is invisible. The Security Bit that controls this function, as well as all other programmed data, is reset only when the device is erased.

## Timing Model

MAX 7000 device timing can be analyzed with MAX+PLUS II software, with a variety of popular industry-standard EDA simulators and timing analyzers, or with the timing model shown in Figure 10. MAX 7000 devices have fixed internal delays that enable the designer to determine the worst-case timing of any design. MAX+PLUS II software provides timing simulation, point-to-point delay prediction, and detailed timing analysis for system-level performance evaluation.

Figure 10. MAX 7000 Timing Model



**Notes:**

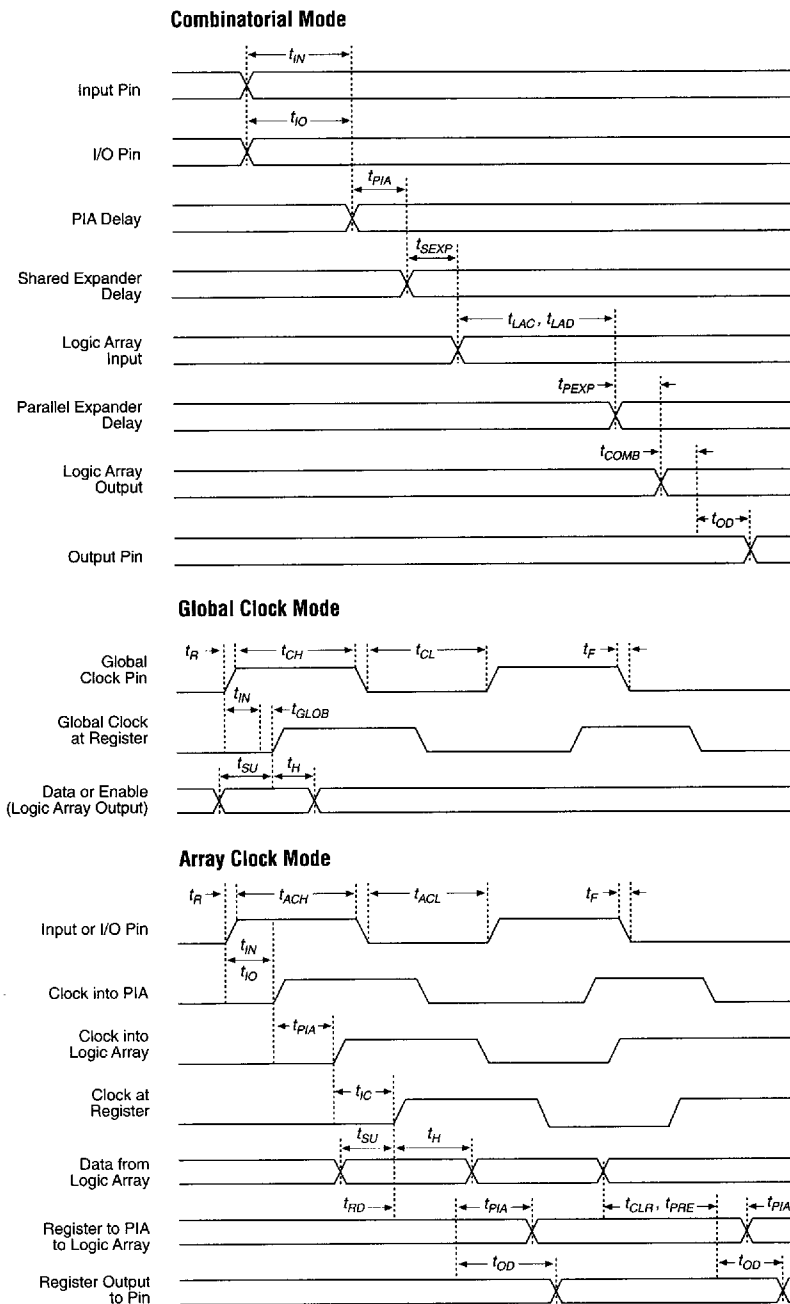
- (1) Not available in 44-pin devices.
- (2) Only available in EPM7128E, EPM7160E, EPM7192E, and EPM7256E devices.

The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 11 shows the internal timing relationship of internal and external delay parameters. See *Application Brief 100 (Understanding Classic, MAX 5000 & MAX 7000 Timing)* in this data book for more information.



Figure 11. Switching Waveforms

$t_R$  &  $t_F < 3$  ns.  
 Inputs are driven at 3 V  
 for a logic high and 0 V  
 for a logic low. All timing  
 characteristics are  
 measured at 1.5 V.

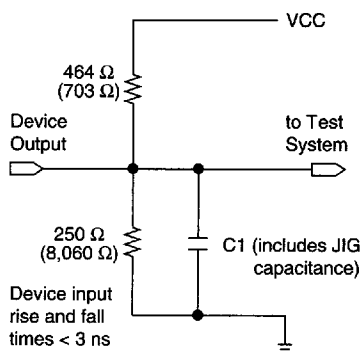


## Generic Testing

MAX 7000 devices are fully functionally tested and guaranteed. Complete testing of each programmable EEPROM bit and all internal logic elements ensures 100% programming yield. AC test measurements are taken under conditions equivalent to those shown in Figure 12. Test patterns can be used and then erased during early stages of the production flow.

**Figure 12. MAX 7000 AC Test Conditions**

*Power supply transients can affect AC measurements. Simultaneous transitions of multiple outputs should be avoided for accurate measurement. Threshold tests must not be performed under AC conditions. Large-amplitude, fast ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result. Numbers in parentheses are for 3.3-V devices.*



## Device Programming

All MAX 7000 devices can be programmed on 486- and Pentium-based PCs with an Altera Logic Programmer card, the Master Programming Unit (MPU), and the appropriate device adapter. The MPU performs continuity checking to ensure adequate electrical contact between the adapter and the device.

The MAX+PLUS II software can use text- or waveform-format test vectors created with the MAX+PLUS II Text or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional behavior of a MAX 7000 device with the results of simulation.

Data I/O and other programming hardware manufacturers also provide programming support for Altera devices. See *Programming Hardware Manufacturers* in this data book for more information.

## QFP Carrier & Development Socket

MAX 7000 devices in QFP packages with 100 or more pins are shipped in special plastic carriers to protect the fragile QFP leads. The carrier is used with a prototype development socket and special programming hardware available from Altera. This carrier technology makes it possible to program, test, erase, and reprogram a device without exposing the leads to mechanical stress. For detailed information, refer to the *QFP Carrier & Development Socket Data Sheet* in this data book.

**MAX 7000 5.0-V Device Absolute Maximum Ratings** Note (1)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply voltage	With respect to GND	-2.0	7.0	V
$V_I$	DC input voltage	Note (2)	-2.0	7.0	V
$I_{OUT}$	DC output current, per pin		-25	25	mA
$T_{STG}$	Storage temperature	No bias	-65	150	°C
$T_{AMB}$	Ambient temperature	Under bias, Note (3)	-65 [-55]	135 [125]	°C
$T_J$	Junction temperature	Under bias, Note (3)		150 [175]	°C

**MAX 7000 5.0-V Device Recommended Operating Conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CCINT}$	Supply voltage of internal logic and input buffers	Notes (4), (5)	4.75 (4.5)	5.25 (5.5)	V
$V_{CCIO}$	Supply voltage of output drivers	5.0-V operation, Notes (4), (5)	4.75 (4.5)	5.25 (5.5)	V
		3.3-V operation, Notes (5), (6)	3.00	3.60	V
$V_I$	Input voltage		0	$V_{CCINT}$	V
$V_O$	Output voltage		0	$V_{CCIO}$	V
$T_A$	Operating temperature	For commercial use	0	70	°C
$T_A$	Operating temperature	For industrial use	-40	85	°C
$T_C$	Case temperature	For military use	-55	125	°C
$t_R$	Input rise time			40	ns
$t_F$	Input fall time			40	ns

**MAX 7000 5.0-V Device DC Operating Conditions** Note (7)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{IH}$	High-level input voltage		2.0	$V_{CCINT} + 0.3$	V
$V_{IL}$	Low-level input voltage		-0.3	0.8	V
$V_{OH}$	5.0-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 4.75$ V	2.4		V
	3.3-V high-level TTL output voltage	$I_{OH} = -4$ mA DC, $V_{CCIO} = 3.0$ V	2.4		V
$V_{OL}$	5.0-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 4.75$ V		0.45	V
	3.3-V low-level TTL output voltage	$I_{OL} = 12$ mA DC, $V_{CCIO} = 3.0$ V		0.45	V
$I_I$	Input leakage current	$V_I = V_{CC}$ or GND	-10	10	μA
$I_{OZ}$	Tri-state output off-state current	$V_O = V_{CC}$ or GND	-40	40	μA

**MAX 7000 5.0-V Device Capacitance: EPM7032, EPM7064 & EPM7096** Note (8)

Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		12	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		12	pF

**MAX 7000 5.0-V Device Capacitance: EPM7128E, EPM7160E, EPM7192E & EPM7256E** Note (8)

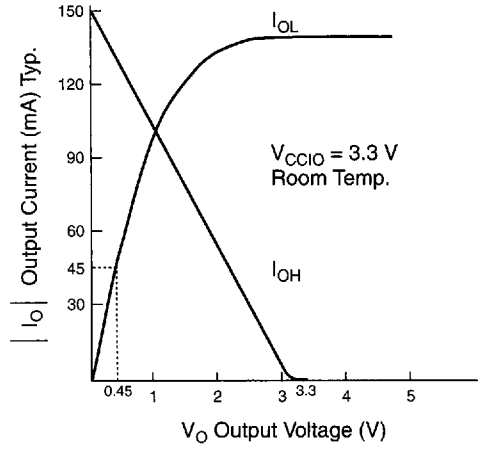
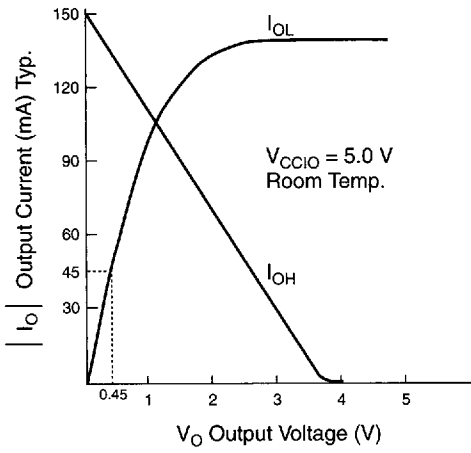
Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input pin capacitance	$V_{IN} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		15	pF
$C_{I/O}$	I/O pin capacitance	$V_{OUT} = 0\text{ V}$ , $f = 1.0\text{ MHz}$		15	pF

**Notes to tables:**

- (1) See *Operating Requirements for Altera Devices* in this data book.
- (2) Minimum DC input is  $-0.3\text{ V}$ . During transitions, the inputs may undershoot to  $-2.0\text{ V}$  or overshoot to  $7.0\text{ V}$  for periods shorter than  $20\text{ ns}$  under no-load conditions.
- (3) Numbers in brackets are for MIL-STD-883-compliant versions only.
- (4) Numbers in parentheses are for military- and industrial-temperature range and MIL-STD-883-compliant versions.
- (5)  $V_{CC}$  must rise monotonically.
- (6) 3.3-V I/O operation is not available for 44-pin packages.
- (7) Operating conditions:  $V_{CCINT} = 5.0\text{ V} \pm 5\%$ ,  $T_A = 0^\circ\text{ C}$  to  $70^\circ\text{ C}$  for commercial use.  
 $V_{CCINT} = 5.0\text{ V} \pm 10\%$ ,  $T_A = -40^\circ\text{ C}$  to  $85^\circ\text{ C}$  for industrial use.  
 $V_{CCINT} = 5.0\text{ V} \pm 10\%$ ,  $T_C = -55^\circ\text{ C}$  to  $125^\circ\text{ C}$  for military use.
- (8) Capacitance measured at  $25^\circ\text{ C}$ . Sample-tested only. The OE1 pin (high-voltage pin during programming) has a maximum capacitance of  $20\text{ pF}$ .

Figure 13 shows typical output drive characteristics of MAX 7000 devices.

**Figure 13. Output Drive Characteristics of MAX 7000 Devices**



MAX 7000 AC Operating Conditions Notes (1), (2)

External Timing Parameters			-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		5		6		7.5	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		5		6		7.5	ns
t <sub>SU</sub>	Global clock setup time		4		5		6		ns
t <sub>H</sub>	Global clock hold time		0		0		0		ns
t <sub>SU</sub>	Global clock setup time of fast input	Note (3)	–		–		3		ns
t <sub>FH</sub>	Global clock hold time of fast input	Note (3)	–		–		0.5		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		3.5		4		4.5	ns
t <sub>CH</sub>	Global clock high time		2		2.5		3		ns
t <sub>CL</sub>	Global clock low time		2		2.5		3		ns
t <sub>ASU</sub>	Array clock setup time		2		2.5		3		ns
t <sub>AH</sub>	Array clock hold time		2		2		2		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		5.5		6.5		7.5	ns
t <sub>ACH</sub>	Array clock high time		2.5		3		3		ns
t <sub>ACL</sub>	Array clock low time		2.5		3		3		ns
t <sub>CNT</sub>	Minimum global clock period			5.6		6.6		8	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	Note (4)	178.6		151.5		125		MHz
t <sub>ACNT</sub>	Minimum array clock period			5.6		6.6		8	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	Note (4)	178.6		151.5		125		MHz
f <sub>MAX</sub>	Maximum clock frequency	Note (5)	250		200		166.7		MHz

Internal Timing Parameters			-5 Speed Grade		-6 Speed Grade		-7 Speed Grade		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{IN}$	Input pad and buffer delay			0.4		0.4		0.5	ns
$t_{IO}$	I/O input pad and buffer delay			0.4		0.4		0.5	ns
$t_{FIN}$	Fast input delay	Note (3)						1	ns
$t_{SEXP}$	Shared expander delay			3		3.5		4	ns
$t_{PEXP}$	Parallel expander delay			0.8		0.8		0.8	ns
$t_{LAD}$	Logic array delay			1.5		2		3	ns
$t_{LAC}$	Logic control array delay			1.5		2		3	ns
$t_{IOE}$	Internal output enable delay	Note (3)						2	ns
$t_{OD1}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (1)		1.5		2		2	ns
$t_{OD2}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)				2.5		2.5	ns
$t_{OD3}$	Output buffer & pad delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Notes (1), (3), (6)						6	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		4		4		4	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		–		4.5		4.5	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		–		–		8	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		4		4		4	ns
$t_{SU}$	Register setup time		2.5		3		3		ns
$t_H$	Register hold time		1.5		1.5		2		ns
$t_{FSU}$	Register setup time of fast input	Note (3)					3		ns
$t_{FH}$	Register hold time of fast input	Note (3)					0.5		ns
$t_{RD}$	Register delay			0.8		0.8		1	ns
$t_{COMB}$	Combinatorial delay			0.8		0.8		1	ns
$t_{IC}$	Array clock delay			2		2.5		3	ns
$t_{EN}$	Register enable time			1.5		2		3	ns
$t_{GLOB}$	Global control delay			0.8		0.8		1	ns
$t_{PRE}$	Register preset time			2		2		2	ns
$t_{CLR}$	Register clear time			2		2		2	ns
$t_{PIA}$	Programmable Interconnect Array delay			0.8		0.8		1	ns
$t_{LPA}$	Low-power adder	Note (7)		8		10		10	ns

<b>External Timing Parameters</b>			<b>-10P Speed Grade</b>		<b>-10 Speed Grade</b>		<b>-12P Speed Grade</b>		<b>-12 Speed Grade</b>		
<b>Symbol</b>	<b>Parameter</b>	<b>Conditions</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Unit</b>
$t_{PD1}$	Input to non-registered output	$C1 = 35 \text{ pF}$		10		10		12		12	ns
$t_{PD2}$	I/O input to non-registered output	$C1 = 35 \text{ pF}$		10		10		12		12	ns
$t_{SU}$	Global clock setup time		7		8		7		10		ns
$t_H$	Global clock hold time		0		0		0		0		ns
$t_{FSU}$	Global clock setup time of fast input	<i>Note (3)</i>	3		3		3		3		ns
$t_{FH}$	Global clock hold time of fast input	<i>Note (3)</i>	0.5		0.5		1		1		ns
$t_{CO1}$	Global clock to output delay	$C1 = 35 \text{ pF}$		5		5		6		6	ns
$t_{CH}$	Global clock high time		4		4		4		4		ns
$t_{CL}$	Global clock low time		4		4		4		4		ns
$t_{ASU}$	Array clock setup time		2		3		3		4		ns
$t_{AH}$	Array clock hold time		3		3		4		4		ns
$t_{ACO1}$	Array clock to output delay	$C1 = 35 \text{ pF}$		10		10		12		12	ns
$t_{ACH}$	Array clock high time		4		4		5		5		ns
$t_{ACL}$	Array clock low time		4		4		5		5		ns
$t_{CNT}$	Minimum global clock period			10		10		11		11	ns
$f_{CNT}$	Maximum internal global clock frequency	<i>Note (4)</i>	100		100		90.9		90.9		MHz
$t_{ACNT}$	Minimum array clock period			10		10		11		11	ns
$f_{ACNT}$	Maximum internal array clock frequency	<i>Note (4)</i>	100		100		90.9		90.9		MHz
$f_{MAX}$	Maximum clock frequency	<i>Note (5)</i>	125		125		125		125		MHz



Internal Timing Parameters			-10P Speed Grade		-10 Speed Grade		-12P Speed Grade		-12 Speed Grade		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Min	Max	Unit
$t_{IN}$	Input pad and buffer delay			0.5		1		1		2	ns
$t_{IO}$	I/O input pad and buffer delay			0.5		1		1		2	ns
$t_{FIN}$	Fast input delay	Note (3)		1		1		1		1	ns
$t_{SEXP}$	Shared expander delay			5		5		7		7	ns
$t_{PEXP}$	Parallel expander delay			0.8		0.8		1		1	ns
$t_{LAD}$	Logic array delay			5		5		7		5	ns
$t_{LAC}$	Logic control array delay			5		5		5		5	ns
$t_{IOE}$	Internal output enable delay	Note (3)		2		2		2		2	ns
$t_{OD1}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (1)		1.5		2		1		3	ns
$t_{OD2}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		2		2.5		2		4	ns
$t_{OD3}$	Output buffer & pad delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Notes (1), (3), (6)		5.5		6		5		7	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		5		5		6		6	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		5.5		5.5		7		7	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		9		9		10		10	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		5		5		6		6	ns
$t_{SU}$	Register setup time		2		3		1		4		ns
$t_H$	Register hold time		3		3		6		4		ns
$t_{FSU}$	Register setup time of fast input	Note (3)	3		3		4		2		ns
$t_{FH}$	Register hold time of fast input	Note (3)	0.5		0.5		0		2		ns
$t_{RD}$	Register delay			2		1		2		1	ns
$t_{COMB}$	Combinatorial delay			2		1		2		1	ns
$t_{IC}$	Array clock delay			5		5		5		5	ns
$t_{EN}$	Register enable time			5		5		7		5	ns
$t_{GLOB}$	Global control delay			1		1		2		0	ns
$t_{PRE}$	Register preset time			3		3		4		3	ns
$t_{CLR}$	Register clear time			3		3		4		3	ns
$t_{PIA}$	Programmable Interconnect Array delay			1		1		1		1	ns
$t_{LPA}$	Low-power adder	Note (7)		11		11		12		12	ns

<i>External Timing Parameters</i>			-15 Speed Grade		-15T Speed Grade		-20 Speed Grade		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
t <sub>PD1</sub>	Input to non-registered output	C1 = 35 pF		15		15		20	ns
t <sub>PD2</sub>	I/O input to non-registered output	C1 = 35 pF		15		15		20	ns
t <sub>SU</sub>	Global clock setup time		11		11		12		ns
t <sub>H</sub>	Global clock hold time		0		0		0		ns
t <sub>FSU</sub>	Global clock setup time of fast input	Note (3)	3		–		5		ns
t <sub>FH</sub>	Global clock hold time of fast input	Note (3)	1		–		2		ns
t <sub>CO1</sub>	Global clock to output delay	C1 = 35 pF		8		8		12	ns
t <sub>CH</sub>	Global clock high time		5		6		6		ns
t <sub>CL</sub>	Global clock low time		5		6		6		ns
t <sub>ASU</sub>	Array clock setup time		4		4		5		ns
t <sub>AH</sub>	Array clock hold time		4		4		5		ns
t <sub>ACO1</sub>	Array clock to output delay	C1 = 35 pF		15		15		20	ns
t <sub>ACH</sub>	Array clock high time		6		6.5		8		ns
t <sub>ACL</sub>	Array clock low time		6		6.5		8		ns
t <sub>CNT</sub>	Minimum global clock period			13		13		16	ns
f <sub>CNT</sub>	Maximum internal global clock frequency	Note (4)	76.9		76.9		62.5		MHz
t <sub>ACNT</sub>	Minimum array clock period			13		13		16	ns
f <sub>ACNT</sub>	Maximum internal array clock frequency	Note (4)	76.9		76.9		62.5		MHz
f <sub>MAX</sub>	Maximum clock frequency	Note (5)	100		83.3		83.3		MHz

Internal Timing Parameters			-15 Speed Grade		-15T Speed Grade		-20 Speed Grade		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{IN}$	Input pad and buffer delay			2		2		3	ns
$t_{IO}$	I/O input pad and buffer delay			2		2		3	ns
$t_{FIN}$	Fast input delay	Note (3)		2		–		4	ns
$t_{SEXP}$	Shared expander delay			8		10		9	ns
$t_{PEXP}$	Parallel expander delay			1		1		2	ns
$t_{LAD}$	Logic array delay			6		6		8	ns
$t_{LAC}$	Logic control array delay			6		6		8	ns
$t_{IOE}$	Internal output enable delay	Note (3)		3		–		4	ns
$t_{OD1}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (1)		4		4		5	ns
$t_{OD2}$	Output buffer & pad delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		5		–		6	ns
$t_{OD3}$	Output buffer & pad delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Notes (3), (6)		8		–		9	ns
$t_{ZX1}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 5.0\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		6		6		10	ns
$t_{ZX2}$	Output buffer enable delay Slow slew rate = off $V_{CCIO} = 3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		7		–		11	ns
$t_{ZX3}$	Output buffer enable delay Slow slew rate = on $V_{CCIO} = 5.0\text{ V}$ or $3.3\text{ V}$	$C1 = 35\text{ pF}$ Note (6)		10		–		14	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5\text{ pF}$		6		6		10	ns
$t_{SU}$	Register setup time		4		4		4		ns
$t_H$	Register hold time		4		4		5		ns
$t_{FSU}$	Register setup time of fast input	Note (3)	2		–		4		ns
$t_{FH}$	Register hold time of fast input	Note (3)	2		–		3		ns
$t_{RD}$	Register delay			1		1		1	ns
$t_{COMB}$	Combinatorial delay			1		1		1	ns
$t_{IC}$	Array clock delay			6		6		8	ns
$t_{EN}$	Register enable time			6		6		8	ns
$t_{GLOB}$	Global control delay			1		1		3	ns
$t_{PRE}$	Register preset time			4		4		4	ns
$t_{CLR}$	Register clear time			4		4		4	ns
$t_{PIA}$	Programmable Interconnect Array delay			2		2		3	ns
$t_{LPA}$	Low-power adder	Note (7)		13		15		15	ns

**Notes to tables:**

- (1) Operating conditions:  
 $V_{CCINT} = 5.0\text{ V} \pm 5\%$ ,  $V_{CCIO} = 5.0\text{ V} \pm 5\%$  (except where noted),  $T_A = 0^\circ\text{ C}$  to  $70^\circ\text{ C}$  for commercial use.  
 $V_{CCINT} = 5.0\text{ V} \pm 10\%$ ,  $V_{CCIO} = 5.0\text{ V} \pm 10\%$  (except where noted),  $T_A = -40^\circ\text{ C}$  to  $85^\circ\text{ C}$  for industrial use.  
 $V_{CCINT} = 5.0\text{ V} \pm 10\%$ ,  $V_{CCIO} = 5.0\text{ V} \pm 10\%$  (except where noted),  $T_C = -55^\circ\text{ C}$  to  $125^\circ\text{ C}$  for military use.
- (2) Timing parameters for some devices are preliminary. See Table 2 on page 156 of this data sheet for available speed grades and packages.
- (3) This parameter applies only to MAX 7000E devices (EPM7128E, EPM7160E, EPM7192E, and EPM7256E).
- (4) Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- (6) Operating conditions:  $V_{CCIO} = 3.3\text{ V} \pm 10\%$  for commercial, industrial, and military use.
- (7) The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in the low-power mode.

## 3.3-V EPM7032V

The EPM7032V device is a high-performance MAX 7000 device that meets the low power and voltage requirements of 3.3-V applications ranging from notebook computers to battery-operated, hand-held equipment. The EPM7032V provides in-system speeds of up to 90.9 MHz and propagation delays of 12 ns. It is available in 44-pin reprogrammable PLCC or TQFP packages and can accommodate designs with up to 36 inputs and 32 outputs.

### Power Management

The 3.3-V operation of the EPM7032V offers power savings of 30% to 50% over the 5.0-V operation of the EPM7032. Power-saving features of the EPM7032V include a programmable power-saving mode and a power-down mode.

### Power-Down Mode

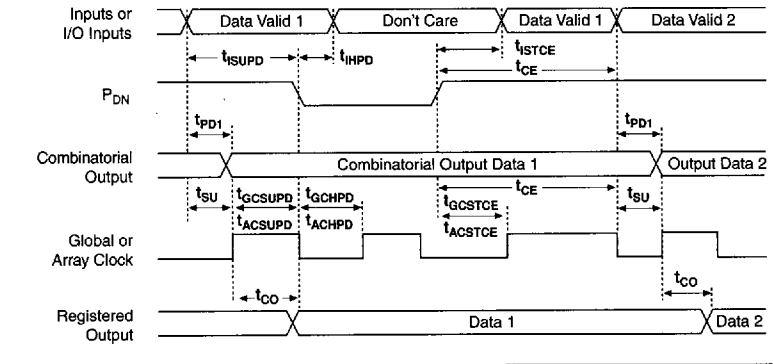
The EPM7032V device provides a unique power-down mode that allows the device to consume near-zero power (typically 50  $\mu\text{A}$ ). The power-down mode is controlled externally by the dedicated power-down pin (PDn). When PDn is asserted (active low), the power-down sequence latches all input pins, internal logic, and output pins of the EPM7032V device, preserving their present state. Output pins maintain their present low, high, or tri-state value while in power-down mode.

Once in power-down mode, any or all of the inputs, including Clocks, can be toggled without affecting the state of the device. Since internal latches are used to ensure that the proper state exists during power-down mode, the external inputs and Clocks must meet certain setup and hold time requirements. See Figure 14 and the "Power-Down Timing Parameters" and "Chip Enable Timing Parameters" tables on page 189 of this data sheet.

**Figure 14. Power-Down Mode Switching Waveforms**

The switching waveforms for the EPM7032V are identical to those of the 5.0-V EPM7032 in all modes, except for the additional power-down mode shown here.

$t_R$  &  $t_F < 3$  ns. Inputs are driven at 3 V for a logic high and 0 V for a logic low. All timing characteristics are measured at 1.5 V.



When the  $P_{DN}$  signal is brought high, the device is enabled and the combinatorial outputs respond to the present input conditions within the specified chip-enable delay ( $t_{CE}$ ). Registered outputs respond to Clock transitions within  $t_{CE}$ . Clocking the device during the chip-enable sequence can cause the data to change inside the chip if a Clock transition occurs during certain intervals of the chip-enable or chip-disable sequences. All Clocks should be gated to prevent Clock transitions during the Clock setup time ( $t_{GCSUPD}$  or  $t_{ACSUPD}$ ) and during the chip-enable setup time ( $t_{GCSCE}$  or  $t_{ACSCE}$ ), as shown in Figure 14.

All registers in the EPM7032V provide Clock Enable control, which makes it easy to disable Clocks. If output signals must be frozen in a high-impedance state during power-down, the associated Output Enable signal must be asserted, the system Clock must be removed, and the  $P_{DN}$  pin must be asserted. To reactivate the device, the sequence is reversed. For some systems, it may be more appropriate to switch the order of the Clock and Output Enable controls.

All power-down/chip-enable timing parameters are computed from external input or I/O pins, with the macrocell Turbo Bit turned on, and without the use of parallel expanders. For macrocells in low-power mode (Turbo Bit off), the low-power adder,  $t_{LPA}$ , must be added to the power-down/chip-enable timing parameters, which include the data paths  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{ACH}$ , and  $t_{SEXP}$ . For macrocells that use shared or parallel expanders,  $t_{SEXP}$  or  $t_{PEXP}$  must be added. For data or Clock paths that use more than one logic array delay, the worst-case data or Clock delay must be added to the respective power-down/chip-enable parameters. Actual worst-case timing of data and Clock paths can be calculated with the MAX+PLUS II Simulator or Timing Analyzer, or with other industry-standard EDA verification tools.

**MAX 7000 3.3-V Device Absolute Maximum Ratings** Note (1)

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply voltage	With respect to GND, Note (2)	-2.0	5.6	V
$V_I$	DC input voltage	With respect to GND, Note (2)	-2.0	5.6	V
$I_{OUT}$	DC output current per pin		-25	25	mA
$T_{STG}$	Storage temperature	No bias	-65	150	°C
$T_{AMB}$	Ambient temperature	Under bias	-65	135	°C
$T_J$	Junction temperature	Under bias		150	°C
$P_D$	Power dissipation			1,000	mW
$I_{MAX}$	DC $V_{CC}$ or GND current			300	mA

**MAX 7000 3.3-V Device Recommended Operating Conditions**

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	Supply voltage	Note (3)	3.0	3.6	V
$V_I$	Input voltage		0	$V_{CC}$	V
$V_O$	Output voltage		0	$V_{CC}$	V
$T_A$	Operating temperature	For commercial use	0	70	°C
$T_A$	Operating temperature	For industrial use	-40	85	°C
$t_R$	Input rise time			40	ns
$t_F$	Input fall time			40	ns

**MAX 7000 3.3-V Device DC Operating Conditions** Notes (4), (5)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{IH}$	High-level input voltage		2.0		$V_{CC} + 0.3$	V
$V_{IL}$	Low-level input voltage		-0.3		0.8	V
$V_{OH}$	High-level TTL output voltage	$I_{OH} = -0.1$ mA DC	$V_{CC} - 0.2$			V
$V_{OL}$	Low-level output voltage	$I_{OL} = 4$ mA DC			0.45	V
$I_I$	Input leakage current	$V_I = V_{CC}$ or GND	-10		10	$\mu$ A
$I_{OZ}$	Tri-state output off-state current	$V_O = V_{CC}$ or GND	-10		10	$\mu$ A
$I_{CC0}$	$V_{CC}$ supply current (standby, power-down mode)	Note (6)		2	150	$\mu$ A
$I_{CC1}$	$V_{CC}$ supply current (standby, low-power mode)	$V_I =$ GND, no load, Note (6)		10	20	mA
$I_{CC2}$	$V_{CC}$ supply current (active, low-power mode)	$V_I =$ GND, no load, $f = 1.0$ MHz, Note (6)		15	25	mA

**MAX 7000 3.3-V Device Capacitance** Note (7)

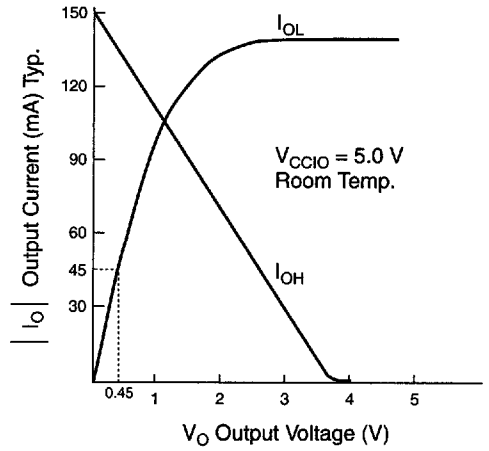
Symbol	Parameter	Conditions	Min	Max	Unit
$C_{IN}$	Input capacitance	$V_{IN} = 0$ V, $f = 1.0$ MHz		12	pF
$C_{OUT}$	Output capacitance	$V_{OUT} = 0$ V, $f = 1.0$ MHz		12	pF

**Notes to tables:**

- See *Operating Requirements for Altera Devices* in this data book.
- Minimum DC input is -0.3 V. During transitions, the inputs may undershoot to -2.0 V or overshoot to  $V_{CC} + 2.0$  V for periods shorter than 20 ns under no-load conditions.
- $V_{CC}$  must rise monotonically.
- Typical values are for  $T_A = 25^\circ$  C and  $V_{CC} = 3.3$  V.
- Operating conditions:  $V_{CC} = 3.3$  V  $\pm$  10%,  $T_A = 0^\circ$  C to  $70^\circ$  C for commercial use.  
 $V_{CC} = 3.3$  V  $\pm$  10%,  $T_A = -40^\circ$  C to  $85^\circ$  C for industrial use.
- Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.  $I_{CC}$  is measured at  $0^\circ$  C.
- Capacitance is measured at  $25^\circ$  C. Sample-tested only. The OE1n pin (high-voltage pin during programming) has a maximum capacitance of 20 pF.

Figure 15 shows typical output drive characteristics of the EPM7032V.

**Figure 15. EPM7032V Output Drive Characteristics**





## EPM7032V AC Operating Conditions Note (1)

External Timing Parameters			EPM7032V-12		EPM7032V-15		EPM7032V-20		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{PD1}$	Input to non-registered output	$C1 = 35 \text{ pF}$		12		15		20	ns
$t_{PD2}$	I/O input to non-registered output	$C1 = 35 \text{ pF}$		12		15		20	ns
$t_{SU}$	Global clock setup time		10		11		12		ns
$t_H$	Global clock hold time		0		0		0		ns
$t_{CO1}$	Global clock to output delay	$C1 = 35 \text{ pF}$		7		8		12	ns
$t_{CH}$	Global clock high time		4		5		6		ns
$t_{CL}$	Global clock low time		4		5		6		ns
$t_{ASU}$	Array clock setup time		4		4		5		ns
$t_{AH}$	Array clock hold time		4		4		5		ns
$t_{ACO1}$	Array clock to output delay	$C1 = 35 \text{ pF}$		12		15		20	ns
$t_{ACH}$	Array clock high time		5		6		8		ns
$t_{ACL}$	Array clock low time		5		6		8		ns
$t_{CNT}$	Minimum global clock period			11		13		16	ns
$f_{CNT}$	Maximum internal global clock frequency	Note (2)	90.9		76.9		62.5		MHz
$t_{ACNT}$	Minimum array clock period			11		13		16	ns
$f_{ACNT}$	Maximum internal array clock frequency	Note (2)	90.9		76.9		62.5		MHz
$f_{MAX}$	Maximum clock frequency	Note (3)	125		100		83.3		MHz

## EPM7032V AC Operating Conditions Note (1)

Internal Timing Parameters			EPM7032V-12		EPM7032V-15		EPM7032V-20		
Symbol	Parameter	Conditions	Min	Max	Min	Max	Min	Max	Unit
$t_{IN}$	Input pad and buffer delay			3		2		3	ns
$t_{IO}$	I/O input pad and buffer delay			3		2		3	ns
$t_{SEXP}$	Shared expander delay			7		8		9	ns
$t_{PEXP}$	Parallel expander delay			1		1		2	ns
$t_{LAD}$	Logic array delay			4		6		8	ns
$t_{LAC}$	Logic control array delay			4		6		8	ns
$t_{OD}$	Output buffer and pad delay	$C1 = 35 \text{ pF}$		3		4		5	ns
$t_{ZX}$	Output buffer enable delay	$C1 = 35 \text{ pF}$		6		6		9	ns
$t_{XZ}$	Output buffer disable delay	$C1 = 5 \text{ pF}$		6		6		9	ns
$t_{SU}$	Register setup time		5		4		4		ns
$t_{H}$	Register hold time		4		4		5		ns
$t_{RD}$	Register delay			1		1		1	ns
$t_{COMB}$	Combinatorial delay			1		1		1	ns
$t_{IC}$	Array clock delay			4		6		8	ns
$t_{EN}$	Register enable time			4		6		8	ns
$t_{GLOB}$	Global control delay			0		1		3	ns
$t_{PRE}$	Register preset time			3		4		4	ns
$t_{CLR}$	Register clear time			3		4		4	ns
$t_{PIA}$	Programmable Interconnect Array delay			1		2		3	ns
$t_{LPA}$	Low-power adder	Note (4)		15		17		20	ns

## Notes to tables:

- Operating conditions:  $V_{CC} = 3.3 \text{ V} \pm 10\%$ ,  $T_A = 0^\circ \text{ C}$  to  $70^\circ \text{ C}$  for commercial use.  
 $V_{CC} = 3.3 \text{ V} \pm 10\%$ ,  $T_A = -40^\circ \text{ C}$  to  $85^\circ \text{ C}$  for industrial use.
- Measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.  $I_{CC}$  is measured at  $0^\circ \text{ C}$ .
- The  $f_{MAX}$  values represent the highest frequency for pipelined data.
- The  $t_{LPA}$  parameter must be added to the  $t_{LAD}$ ,  $t_{LAC}$ ,  $t_{IC}$ ,  $t_{ACL}$ ,  $t_{EN}$ , and  $t_{SEXP}$  parameters for macrocells running in low-power mode.

**MAX 7000 3.3-V Device Power-Down/Chip-Enable Timing Parameters**

<b>Power-Down Timing Parameters</b>		EPM7032V-12		EPM7032V-15		EPM7032V-20		
<b>Symbol</b>	<b>Parameter</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Unit</b>
$t_{\text{SUPD}}$	Input or I/O input setup time before power down	30		30		35		ns
$t_{\text{HPD}}$	Input or I/O input hold time after power down	0		0		0		ns
$t_{\text{GCSUPD}}$	Global clock setup time before power down	20		20		25		ns
$t_{\text{GCHPD}}$	Global clock hold time after power down	0		0		0		ns
$t_{\text{ACSUPD}}$	Array clock setup time before power down	30		30		35		ns
$t_{\text{ACHPD}}$	Array clock hold time after power down	0		0		0		ns
$t_{\text{HPD}}$	Minimum high pulse width of power-down pin	800		800		900		ns
$t_{\text{LPD}}$	Minimum low pulse width of power-down pin	800		800		900		ns
$t_{\text{PDOWN}}$	Power down delay		800		800		900	ns

<b>Chip-Enable Timing Parameters</b>		EPM7032V-12		EPM7032V-15		EPM7032V-20		
<b>Symbol</b>	<b>Parameter</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Min</b>	<b>Max</b>	<b>Unit</b>
$t_{\text{STCE}}$	Input or I/O input stable after chip enable		60		60		70	ns
$t_{\text{GCSTCE}}$	Global clock stable after chip enable		60		60		70	ns
$t_{\text{ACSTCE}}$	Array clock stable after chip enable		60		60		70	ns
$t_{\text{CE}}$	Data stable after chip enable		700		700		800	ns

## Calculating the Supply Current

Supply current ( $I_{CC}$ ) versus frequency ( $f_{MAX}$ ) for MAX 7000 devices is calculated with the following equation:

$$I_{CC} = I_{CC\text{OUTPUT}} + I_{CC\text{ACTIVE}}$$

The  $I_{CC\text{OUTPUT}}$  value, which depends on the device output load characteristics and switching frequency, can be calculated using the guidelines given in *Operating Requirements for Altera Devices* in this data book. The  $I_{CC\text{ACTIVE}}$  value depends on the switching frequency and the application logic.

The  $I_{CC\text{ACTIVE}}$  value is calculated with the following equation:

$$I_{CC\text{ACTIVE}} = (A \times MC_{\text{TON}}) + (B \times MC_{\text{TOFF}}) + (C \times MC) \times f_{\text{MAX}}$$

The parameters for this equation are:

- $MC_{\text{TON}}$  = number of macrocells used with Turbo Bit on
- $MC_{\text{TOFF}}$  = number of macrocells used with Turbo Bit off
- $MC$  = total number of macrocells used in the design  
( $MC_{\text{TON}} + MC_{\text{TOFF}}$ )
- $f_{\text{MAX}}$  = highest Clock frequency to the device

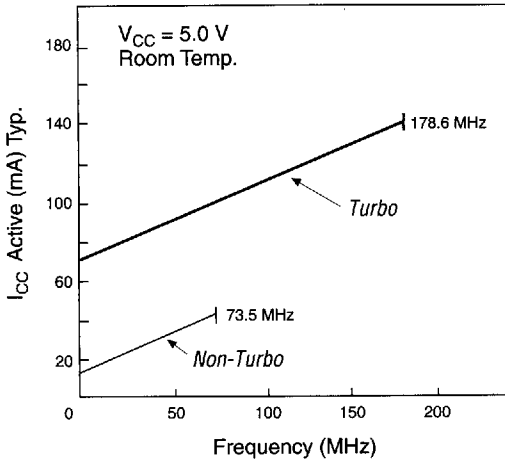
Table 4 lists the values of constants A, B, and C.

Device	Constant A	Constant B	Constant C
EPM7032	2.20	0.55	0.0180
EPM7032V	0.98	0.42	0.0060
EPM7064	1.92	0.78	0.0180
EPM7096	1.92	0.78	0.0180
EPM7128E	1.38	0.57	0.0120
EPM7160E	1.38	0.57	0.0120
EPM7192E	1.38	0.57	0.0120
EPM7256E	1.38	0.57	0.0120

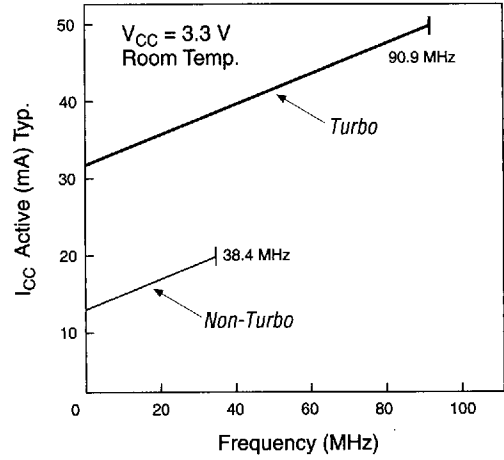
This calculation provides an  $I_{CC}$  estimate based on typical conditions using a typical pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual  $I_{CC}$  should be verified during operation since this measurement is sensitive to the actual pattern in the device and the environmental operating conditions. Figure 16 shows typical supply current versus frequency of the MAX 7000 devices listed in Table 4.

Figure 16.  $I_{CC}$  vs. Frequency of MAX 7000 Devices (Part 1 of 2)

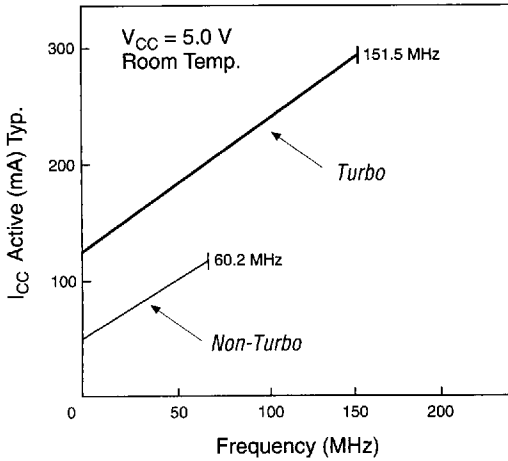
EPM7032



EPM7032V



EPM7064



EPM7096

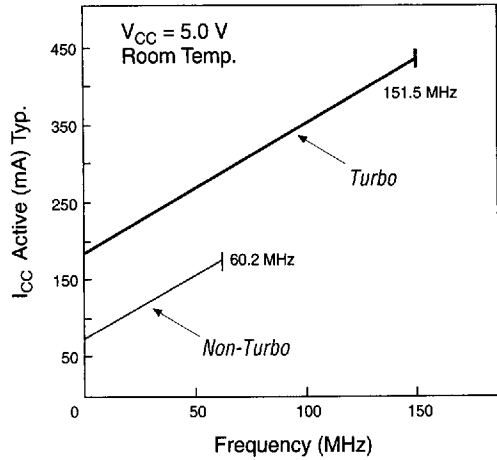
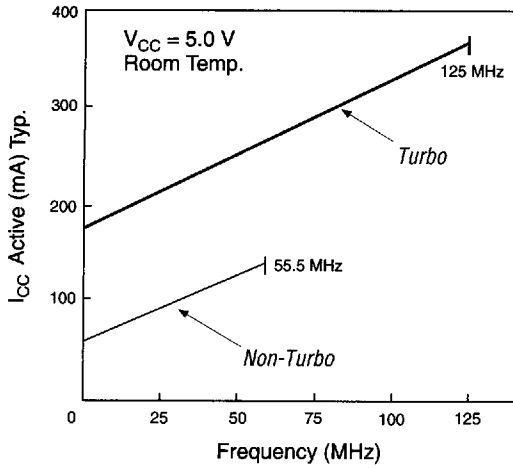
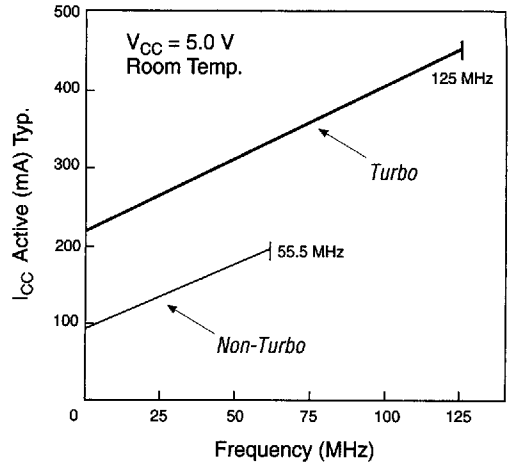


Figure 16.  $I_{CC}$  vs. Frequency of MAX 7000 Devices (Part 2 of 2)

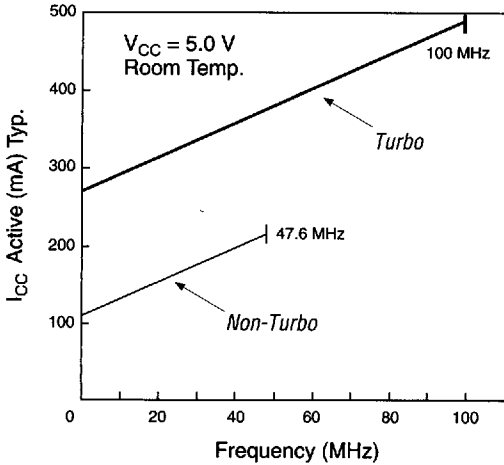
EPM7128E



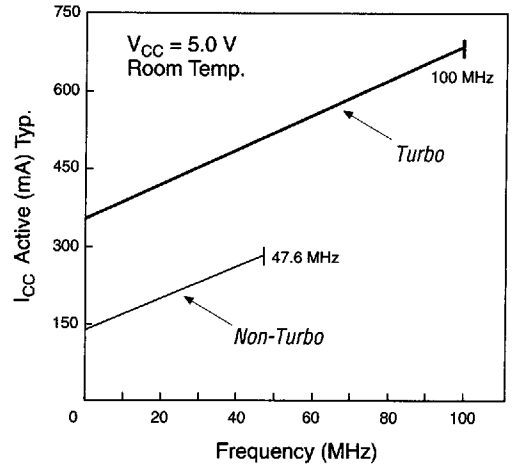
EPM7160E



EPM7192E



EPM7256E



## Device Pin-Outs

Tables 5 through 18 show the pin names and numbers of MAX 7000 device packages.

**Table 5. EPM7032 & EPM7032V Dedicated Pin-Outs**

Dedicated Pin	44-Pin J-Lead	44-Pin QFP
INPUT/GCLK	43	37
INPUT/GCLR <sub>n</sub>	1	39
INPUT/OE1 <sub>n</sub>	44	38
INPUT/OE2 <sub>n</sub>	2	40
GND	10, 22, 30, 42	4, 16, 24, 36
VCC	3, 15, 23, 35	9, 17, 29, 41
No Connect (N.C.)	–	–
Total User I/O Pins	32	32

**Table 6. EPM7032 & EPM7032V I/O Pin-Outs**

MC	LAB	44-Pin J-Lead	44-Pin QFP	MC	LAB	44-Pin J-Lead	44-Pin QFP
1	A	4	42	17	B	41	35
2	A	5	43	18	B	40	34
3	A	6	44	19	B	39	33
4	A	7	1	20	B	38	32
5	A	8	2	21	B	37	31
6	A	9	3	22	B	36	30
7	A	11	5	23	B	34	28
8	A	12	6	24	B	33	27
9	A	13	7	25	B	32	26
10	A	14	8	26	B	31	25
11	A	16	10	27	B	29	23
12	A	17	11	28	B	28	22
13	A	18	12	29	B	27	21
14	A	19	13	30	B	26	20
15	A	20	14	31	B	25	19
16	A	21	15	32	B	24	18

**Table 7. EPM7064 Dedicated Pin-Outs**

Dedicated Pin	44-Pin J-Lead	44-Pin QFP	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP
INPUT/GCLK	43	37	67	83	89
INPUT/GCLRn	1	39	1	1	91
INPUT/OE1n	44	38	68	84	90
INPUT/OE2n	2	40	2	2	92
GND	10, 22, 30, 42	4, 16, 24, 36	6, 16, 26, 34, 38, 48, 58, 66	7, 19, 32, 42, 47, 59, 72, 82	13, 28, 40, 45, 61, 76, 88, 97
VCCINT (5.0 V only)	3, 15, 23, 35	9, 17, 29, 41	3, 35	3, 43	41, 93
VCCIO (3.3 V or 5.0 V)	—	—	11, 21, 31, 43, 53, 63	13, 26, 38, 53, 66, 78	5, 20, 36, 53, 68, 84
No Connect (N.C.)	—	—	—	—	1, 2, 7, 9, 24, 26, 29, 30, 51, 52, 55, 57, 72, 74, 79, 80
Total User I/O Pins	32	32	48	64	64



Table 8. EPM7064 I/O Pin-Outs

MC	LAB	44-Pin J-Lead	44-Pin QFP	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP	MC	LAB	44-Pin J-Lead	44-Pin QFP	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP
1	A	12	6	18	22	16	17	B	21	15	33	41	39
2	A	—	—	—	21	15	18	B	—	—	—	40	38
3	A	11	5	17	20	14	19	B	20	14	32	39	37
4	A	9	3	15	18	12	20	B	19	13	30	37	35
5	A	8	2	14	17	11	21	B	18	12	29	36	34
6	A	—	—	13	16	10	22	B	—	—	28	35	33
7	A	—	—	—	15	8	23	B	—	—	—	34	32
8	A	7	1	12	14	6	24	B	17	11	27	33	31
9	A	—	—	10	12	4	25	B	16	10	25	31	27
10	A	—	—	—	11	3	26	B	—	—	—	30	25
11	A	6	44	9	10	100	27	B	—	—	24	29	23
12	A	—	—	8	9	99	28	B	—	—	23	28	22
13	A	—	—	7	8	98	29	B	—	—	22	27	21
14	A	5	43	5	6	96	30	B	14	8	20	25	19
15	A	—	—	—	5	95	31	B	—	—	—	24	18
16	A	4	42	4	4	94	32	B	13	7	19	23	17
33	C	24	18	36	44	42	49	D	33	27	51	63	65
34	C	—	—	—	45	43	50	D	—	—	—	64	66
35	C	25	19	37	46	44	51	D	34	28	52	65	67
36	C	26	20	39	48	46	52	D	36	30	54	67	69
37	C	27	21	40	49	47	53	D	37	31	55	68	70
38	C	—	—	41	50	48	54	D	—	—	56	69	71
39	C	—	—	—	51	49	55	D	—	—	—	70	73
40	C	28	22	42	52	50	56	D	38	32	57	71	75
41	C	29	23	44	54	54	57	D	39	33	59	73	77
42	C	—	—	—	55	56	58	D	—	—	—	74	78
43	C	—	—	45	56	58	59	D	—	—	60	75	81
44	C	—	—	46	57	59	60	D	—	—	61	76	82
45	C	—	—	47	58	60	61	D	—	—	62	77	83
46	C	31	25	49	60	62	62	D	40	34	64	79	85
47	C	—	—	—	61	63	63	D	—	—	—	80	86
48	C	32	26	50	62	64	64	D	41	35	65	81	87

**Table 9. EPM7096 Dedicated Pin-Outs**

Dedicated Pin	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP
INPUT/GCLK	67	83	89
INPUT/GCLR <sub>n</sub>	1	1	91
INPUT/OE1 <sub>n</sub>	68	84	90
INPUT/OE2 <sub>n</sub>	2	2	92
GND	6, 16, 26, 34, 38, 48, 58, 66	7, 19, 32, 42, 47, 59, 72, 82	13, 28, 40, 45, 61, 76, 88, 97
VCCINT (5.0 V only)	3, 35	3, 43	41, 93
VCCIO (3.3 V or 5.0 V)	11, 21, 31, 43, 53, 63	13, 26, 38, 53, 66, 78	5, 20, 36, 53, 68, 84
No Connect (N.C.)	–	6, 39, 46, 79	9, 24, 37, 44, 57, 72, 85, 96
Total User I/O Pins	48	60	72

**Table 10. EPM7096 I/O Pin-Outs (Part 1 of 2)**

MC	LAB	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP	MC	LAB	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP
1	A	13	16	8	17	B	23	28	23
2	A	–	–	–	18	B	–	–	–
3	A	–	15	7	19	B	22	27	22
4	A	12	14	6	20	B	–	–	21
5	A	–	–	4	21	B	20	25	19
6	A	10	12	3	22	B	–	24	18
7	A	–	–	–	23	B	–	–	–
8	A	9	11	2	24	B	19	23	17
9	A	8	10	1	25	B	18	22	16
10	A	–	–	–	26	B	–	–	–
11	A	–	9	100	27	B	17	21	15
12	A	7	8	99	28	B	–	20	14
13	A	–	–	98	29	B	15	18	12
14	A	5	5	95	30	B	–	–	11
15	A	–	–	–	31	B	–	–	–
16	A	4	4	94	32	B	14	17	10

Table 10. EPM7096 I/O Pin-Outs (Part 2 of 2)

MC	LAB	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP	MC	LAB	68-Pin J-Lead	84-Pin J-Lead	100-Pin QFP
33	C	33	41	39	49	D	36	44	42
34	C	-	-	-	50	D	-	-	-
35	C	32	40	38	51	D	37	45	43
36	C	-	-	35	52	D	-	-	46
37	C	30	37	34	53	D	39	48	47
38	C	-	36	33	54	D	-	49	48
39	C	-	-	-	55	D	-	-	-
40	C	29	35	32	56	D	40	50	49
41	C	28	34	31	57	D	41	51	50
42	C	-	-	-	58	D	-	-	-
43	C	27	33	30	59	D	42	52	51
44	C	-	-	29	60	D	-	-	52
45	C	25	31	27	61	D	44	54	54
46	C	-	30	26	62	D	-	55	55
47	C	-	-	-	63	D	-	-	-
48	C	24	29	25	64	D	45	56	56
65	E	46	57	58	81	F	56	69	73
66	E	-	-	-	82	F	-	-	-
67	E	47	58	59	83	F	-	70	74
68	E	-	-	60	84	F	57	71	75
69	E	49	60	62	85	F	-	-	77
70	E	-	61	63	86	F	59	73	78
71	E	-	-	-	87	F	-	-	-
72	E	50	62	64	88	F	60	74	79
73	E	51	63	65	89	F	61	75	80
74	E	-	-	-	90	F	-	-	-
75	E	52	64	66	91	F	-	76	81
76	E	-	65	67	92	F	62	77	82
77	E	54	67	69	93	F	-	-	83
78	E	-	-	70	94	F	64	80	86
79	E	-	-	-	95	F	-	-	-
80	E	55	68	71	96	F	65	81	87

**Table 11. EPM7128E Dedicated Pin-Outs**

Dedicated Pin	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
INPUT/GCLK1	83	89	139
INPUT/GCLR <sub>n</sub>	1	91	141
INPUT/OE1	84	90	140
INPUT/OE2/GCLK2	2	92	142
GND	7, 19, 32, 42, 47, 59, 72, 82	13, 28, 40, 45, 61, 76, 88, 97	17, 42, 60, 66, 95, 113, 138, 148
VCCINT (5.0 V only)	3, 43	41, 93	61, 143
VCCIO (3.3 V or 5.0 V)	13, 26, 38, 53, 66, 78	5, 20, 36, 53, 68, 84	8, 26, 55, 79, 104, 133
No Connect (N.C.)	—	—	1, 2, 3, 4, 5, 6, 7, 34, 35, 36, 37, 38, 39, 40, 44, 45, 46, 47, 74, 75, 76, 77, 81, 82, 83, 84, 85, 86, 87, 114, 115, 116, 117, 118, 119, 120, 124, 125, 126, 127, 154, 155, 156, 157
Total User I/O Pins	64	80	96

Table 12. EPM7128E I/O Pin-Outs (Part 1 of 2)

MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP	MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
1	A	—	4	160	17	B	22	16	21
2	A	—	—	—	18	B	—	—	—
3	A	12	3	159	19	B	21	15	20
4	A	—	—	158	20	B	—	—	19
5	A	11	2	153	21	B	20	14	18
6	A	10	1	152	22	B	—	12	16
7	A	—	—	—	23	B	—	—	—
8	A	9	100	151	24	B	18	11	15
9	A	—	99	150	25	B	17	10	14
10	A	—	—	—	26	B	—	—	—
11	A	8	98	149	27	B	16	9	13
12	A	—	—	147	28	B	—	—	12
13	A	6	96	146	29	B	15	8	11
14	A	5	95	145	30	B	—	7	10
15	A	—	—	—	31	B	—	—	—
16	A	4	94	144	32	B	14	6	9
33	C	—	27	41	49	D	41	39	59
34	C	—	—	—	50	D	—	—	—
35	C	31	26	33	51	D	40	38	58
36	C	—	—	32	52	D	—	—	57
37	C	30	25	31	53	D	39	37	56
38	C	29	24	30	54	D	—	35	54
39	C	—	—	—	55	D	—	—	—
40	C	28	23	29	56	D	37	34	53
41	C	—	22	28	57	D	36	33	52
42	C	—	—	—	58	D	—	—	—
43	C	27	21	27	59	D	35	32	51
44	C	—	—	25	60	D	—	—	50
45	C	25	19	24	61	D	34	31	49
46	C	24	18	23	62	D	—	30	48
47	C	—	—	—	63	D	—	—	—
48	C	23	17	22	64	D	33	29	43

**Table 12. EPM7128E I/O Pin-Outs (Part 2 of 2)**

MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP	MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
65	E	44	42	62	81	F	—	54	80
66	E	—	—	—	82	F	—	—	—
67	E	45	43	63	83	F	54	55	88
68	E	—	—	64	84	F	—	—	89
69	E	46	44	65	85	F	55	56	90
70	E	—	46	67	86	F	56	57	91
71	E	—	—	—	87	F	—	—	—
72	E	48	47	68	88	F	57	58	92
73	E	49	48	69	89	F	—	59	93
74	E	—	—	—	90	F	—	—	—
75	E	50	49	70	91	F	58	60	94
76	E	—	—	71	92	F	—	—	96
77	E	51	50	72	93	F	60	62	97
78	E	—	51	73	94	F	61	63	98
79	E	—	—	—	95	F	—	—	—
80	E	52	52	78	96	F	62	64	99
97	G	63	65	100	113	H	—	77	121
98	G	—	—	—	114	H	—	—	—
99	G	64	66	101	115	H	73	78	122
100	G	—	—	102	116	H	—	—	123
101	G	65	67	103	117	H	74	79	128
102	G	—	69	105	118	H	75	80	129
103	G	—	—	—	119	H	—	—	—
104	G	67	70	106	120	H	76	81	130
105	G	68	71	107	121	H	—	82	131
106	G	—	—	—	122	H	—	—	—
107	G	69	72	108	123	H	77	83	132
108	G	—	—	109	124	H	—	—	134
109	G	70	73	110	125	H	79	85	135
110	G	—	74	111	126	H	80	86	136
111	G	—	—	—	127	H	—	—	—
112	G	71	75	112	128	H	81	87	137

**Table 13. EPM7160E Dedicated Pin-Outs**

Dedicated Pin	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
INPUT/GCLK1	83	89	139
INPUT/GCLR <sub>n</sub>	1	91	141
INPUT/OE1	84	90	140
INPUT/OE2/GCLK2	2	92	142
GND	7, 19, 32, 42, 47, 59, 72, 82	13, 28, 40, 45, 61, 76, 88, 97	17, 42, 60, 66, 95, 113, 138, 148
VCCINT (5.0 V only)	3, 43	41, 93	61, 143
VCCIO (3.3 V or 5.0 V)	13, 26, 38, 53, 66, 78	5, 20, 36, 53, 68, 84	8, 26, 55, 79, 104, 133
No Connect (N.C.)	6, 39, 46, 79	—	1, 2, 3, 4, 5, 6, 34, 35, 36, 37, 38, 39, 40, 45, 46, 47, 74, 75, 76, 81, 82, 83, 84, 85, 86, 87, 115, 116, 117, 118, 119, 120, 124, 125, 126, 127, 154, 155, 156, 157
Total User I/O Pins	60	80	100

Table 14. EPM7160E I/O Pin-Outs (Part 1 of 3)

MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP	MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
1	A	11	2	158	17	B	18	11	15
2	A	-	-	-	18	B	-	-	-
3	A	10	1	153	19	B	17	10	14
4	A	-	-	-	20	B	-	-	-
5	A	-	-	152	21	B	-	-	13
6	A	-	100	151	22	B	-	9	12
7	A	-	-	-	23	B	-	-	-
8	A	9	99	150	24	B	16	8	11
9	A	8	98	149	25	B	15	7	10
10	A	-	-	-	26	B	-	-	-
11	A	5	96	147	27	B	14	6	9
12	A	-	-	-	28	B	-	-	-
13	A	-	-	146	29	B	-	-	7
14	A	-	95	145	30	B	-	4	160
15	A	-	-	-	31	B	-	-	-
16	A	4	94	144	32	B	12	3	159
33	C	-	21	27	49	D	-	-	48
34	C	-	-	-	50	D	-	-	-
35	C	25	19	25	51	D	33	30	44
36	C	-	-	-	52	D	-	-	-
37	C	-	-	24	53	D	-	29	43
38	C	24	18	23	54	D	31	27	41
39	C	-	-	-	55	D	-	-	-
40	C	23	17	22	56	D	30	26	33
41	C	-	12	16	57	D	-	-	32
42	C	-	-	-	58	D	-	-	-
43	C	20	14	18	59	D	29	25	31
44	C	-	-	-	60	D	-	-	-
45	C	-	-	19	61	D	-	24	30
46	C	21	15	20	62	D	28	23	29
47	C	-	-	-	63	D	-	-	-
48	C	22	16	21	64	D	27	22	28



Table 14. EPM7160E I/O Pin-Outs (Part 2 of 3)

MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP	MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
65	E	—	—	59	81	F	—	—	62
66	E	—	—	—	82	F	—	—	—
67	E	41	39	58	83	F	44	42	63
68	E	—	—	—	84	F	—	—	—
69	E	—	38	57	85	F	—	43	64
70	E	40	37	56	86	F	45	44	65
71	E	—	—	—	87	F	—	—	—
72	E	37	35	54	88	F	48	46	67
73	E	—	—	53	89	F	—	—	68
74	E	—	—	—	90	F	—	—	—
75	E	36	34	52	91	F	49	47	69
76	E	—	—	—	92	F	—	—	—
77	E	—	33	51	93	F	—	48	70
78	E	35	32	50	94	F	50	49	71
79	E	—	—	—	95	F	—	—	—
80	E	34	31	49	96	F	51	50	72
97	G	—	—	73	113	H	—	60	94
98	G	—	—	—	114	H	—	—	—
99	G	52	51	77	115	H	60	62	96
100	G	—	—	—	116	H	—	—	—
101	G	—	52	78	117	H	—	—	97
102	G	54	54	80	118	H	61	63	98
103	G	—	—	—	119	H	—	—	—
104	G	55	55	88	120	H	62	64	99
105	G	—	—	89	121	H	—	69	105
106	G	—	—	—	122	H	—	—	—
107	G	56	56	90	123	H	65	67	103
108	G	—	—	—	124	H	—	—	—
109	G	—	57	91	125	H	—	—	102
110	G	57	58	92	126	H	64	66	101
111	G	—	—	—	127	H	—	—	—
112	G	58	59	93	128	H	63	65	100

**Table 14. EPM7160E I/O Pin-Outs (Part 3 of 3)**

MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP	MC	LAB	84-Pin J-Lead	100-Pin QFP	160-Pin QFP
129	I	67	70	106	145	J	74	79	123
130	I	—	—	—	146	J	—	—	—
131	I	68	71	107	147	J	75	80	128
132	I	—	—	—	148	J	—	—	—
133	I	—	—	108	149	J	—	—	129
134	I	—	72	109	150	J	—	81	130
135	I	—	—	—	151	J	—	—	—
136	I	69	73	110	152	J	76	82	131
137	I	70	74	111	153	J	77	83	132
138	I	—	—	—	154	J	—	—	—
139	I	71	75	112	155	J	80	85	134
140	I	—	—	—	156	J	—	—	—
141	I	—	—	114	157	J	—	—	135
142	I	—	77	121	158	J	—	86	136
143	I	—	—	—	159	J	—	—	—
144	I	73	78	122	160	J	81	87	137

**Table 15. EPM7192E Dedicated Pin-Outs**

Dedicated Pin	160-Pin PGA	160-Pin QFP
INPUT/GCLK1	M8	139
INPUT/GCLR <sub>n</sub>	N8	141
INPUT/OE1	P8	140
INPUT/OE2/GCLK2	R8	142
GND	C4, C6, C11, D7, D9, D13, G4, H12, J4, M7, M9, M13, N4, N11	3, 18, 32, 47, 57, 64, 66, 81, 96, 111, 126, 138, 143, 148
VCCINT (5.0 V only)	C7, C9, N7, N9	56, 65, 137, 144
VCCIO (3.3 V or 5.0 V)	C5, C10, C12, D3, G12, H4, J12, M3, N5, N12	10, 25, 40, 55, 74, 89, 103, 118, 133, 155
No Connect (N.C.)	A1, A2, A14, A15, R1, R2, R14, R15	1, 11, 39, 54, 67, 82, 110, 120
Total User I/O Pins	120	120

Table 16. EPM7192E I/O Pin-Outs (Part 1 of 2)

MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP
1	A	M12	156	17	B	L14	8	33	C	H14	21
2	A	—	—	18	B	—	—	34	C	—	—
3	A	P11	154	19	B	M14	7	35	C	J13	20
4	A	—	—	20	B	—	—	36	C	—	—
5	A	P12	153	21	B	M15	6	37	C	H15	19
6	A	P10	152	22	B	N14	5	38	C	J15	17
7	A	—	—	23	B	—	—	39	C	—	—
8	A	R12	151	24	B	N15	4	40	C	J14	16
9	A	N10	150	25	B	P15	2	41	C	K15	15
10	A	—	—	26	B	—	—	42	C	—	—
11	A	R11	149	27	B	N13	160	43	C	K13	14
12	A	—	—	28	B	—	—	44	C	—	—
13	A	R10	147	29	B	P14	159	45	C	L15	13
14	A	P9	146	30	B	P13	158	46	C	K14	12
15	A	—	—	31	B	—	—	47	C	—	—
16	A	R9	145	32	B	R13	157	48	C	L13	9
49	D	D15	33	65	E	B12	45	81	F	D8	60
50	D	—	—	66	E	—	—	82	F	—	—
51	D	E15	31	67	E	B13	44	83	F	A9	59
52	D	—	—	68	E	—	—	84	F	—	—
53	D	E14	30	69	E	C13	43	85	F	C8	58
54	D	F15	29	70	E	B14	42	86	F	B9	53
55	D	—	—	71	E	—	—	87	F	—	—
56	D	F13	28	72	E	C14	41	88	F	A10	52
57	D	G14	27	73	E	D12	38	89	F	B10	51
58	D	—	—	74	E	—	—	90	F	—	—
59	D	F14	26	75	E	B15	37	91	F	A11	50
60	D	—	—	76	E	—	—	92	F	—	—
61	D	G13	24	77	E	D14	36	93	F	B11	49
62	D	G15	23	78	E	C15	35	94	F	A12	48
63	D	—	—	79	E	—	—	95	F	—	—
64	D	H13	22	80	E	E13	34	96	F	A13	46

**Table 16. EPM7192E I/O Pin-Outs (Part 2 of 2)**

MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP	MC	LAB	160-Pin PGA	160-Pin QFP
97	G	A8	61	113	H	A3	76	129	I	E3	88
98	G	—	—	114	H	—	—	130	I	—	—
99	G	B8	62	115	H	B4	77	131	I	F3	90
100	G	—	—	116	H	—	—	132	I	—	—
101	G	A7	63	117	H	B3	78	133	I	E2	91
102	G	A6	68	118	H	C3	79	134	I	F2	92
103	G	—	—	119	H	—	—	135	I	—	—
104	G	B7	69	120	H	B2	80	136	I	E1	93
105	G	A5	70	121	H	B1	83	137	I	G3	94
106	G	—	—	122	H	—	—	138	I	—	—
107	G	B6	71	123	H	C2	84	139	I	F1	95
108	G	—	—	124	H	—	—	140	I	—	—
109	G	A4	72	125	H	C1	85	141	I	G1	97
110	G	B5	73	126	H	D2	86	142	I	G2	98
111	G	—	—	127	H	—	—	143	I	—	—
112	G	D4	75	128	H	D1	87	144	I	H1	99
145	J	H2	100	161	K	L2	113	177	L	R3	125
146	J	—	—	162	K	—	—	178	L	—	—
147	J	J1	101	163	K	N1	114	179	L	R4	127
148	J	—	—	164	K	—	—	180	L	—	—
149	J	H3	102	165	K	L3	115	181	L	M4	128
150	J	J3	104	166	K	P1	116	182	L	R5	129
151	J	—	—	167	K	—	—	183	L	—	—
152	J	K1	105	168	K	M2	117	184	L	P5	130
153	J	J2	106	169	K	N2	119	185	L	R6	131
154	J	—	—	170	K	—	—	186	L	—	—
155	J	K2	107	171	K	P2	121	187	L	P6	132
156	J	—	—	172	K	—	—	188	L	—	—
157	J	K3	108	173	K	N3	122	189	L	N6	134
158	J	L1	109	174	K	P3	123	190	L	R7	135
159	J	—	—	175	K	—	—	191	L	—	—
160	J	M1	112	176	K	P4	124	192	L	P7	136

Table 17. EPM7256E Dedicated Pin-Outs

Dedicated Pin	160-Pin QFP (1)	192-Pin PGA	208-Pin QFP
INPUT/GCLK1	139	P9	184
INPUT/GCLR <sub>n</sub>	141	R9	182
INPUT/OE1	140	T9	183
INPUT/OE2/GCLK2	142	U9	181
GND	3, 18, 32, 47, 57, 64, 66, 81, 96, 111, 126, 138, 143, 148	C7, C13, D4, D8, D10, G14, H4, K14, L4, P8, P10, P15, R4, R11	14, 32, 50, 72, 75, 82, 94, 116, 134, 152, 174, 180, 185, 200
VCCINT (5.0 V only)	56, 65, 137, 144	D7, D11, P7, P11	74, 83, 179, 186
VCCIO (3.3 V or 5.0 V)	10, 25, 40, 55, 74, 89, 103, 118, 133, 155	C5, C11, D14, G4, H14, K4, L14, P3, R5, R14	5, 23, 41, 63, 85, 107, 125, 143, 165, 191
No Connect (N.C.)	—	—	1, 2, 51, 52, 53, 54, 103, 104, 105, 106, 155, 156, 157, 158, 207, 208.
Total User I/O Pins	128	160	160

**Note:**

- (1) Be sure to perform a complete thermal analysis before committing a design to this device package. See *Operating Requirements for Altera Devices* in this data book for more information.

Table 18. EPM7256E I/O Pin-Outs (Part 1 of 4)

MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP	MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP
1	A	2	U17	153	17	B	12	N17	141
2	A	-	-	-	18	B	-	-	-
3	A	1	R16	154	19	B	11	M16	142
4	A	-	-	-	20	B	-	-	-
5	A	160	P14	159	21	B	9	M15	144
6	A	-	U16	160	22	B	-	P17	145
7	A	-	-	-	23	B	-	-	-
8	A	159	R15	161	24	B	8	N16	146
9	A	158	U15	162	25	B	7	R17	147
10	A	-	-	-	26	B	-	-	-
11	A	157	T15	163	27	B	6	P16	148
12	A	-	-	-	28	B	-	-	-
13	A	156	U14	164	29	B	5	T17	149
14	A	-	U13	166	30	B	-	N15	150
15	A	-	-	-	31	B	-	-	-
16	A	154	T14	167	32	B	4	T16	151
33	C	39	B17	108	49	D	49	A14	92
34	C	-	-	-	50	D	-	-	-
35	C	38	C15	109	51	D	48	B12	93
36	C	-	-	-	52	D	-	-	-
37	C	37	C17	110	53	D	46	B13	95
38	C	-	C16	111	54	D	-	A15	96
39	C	-	-	-	55	D	-	-	-
40	C	36	D17	112	56	D	45	B14	97
41	C	35	D15	113	57	D	44	A16	98
42	C	-	-	-	58	D	-	-	-
43	C	34	E17	114	59	D	43	C14	99
44	C	-	-	-	60	D	-	-	-
45	C	33	D16	115	61	D	42	B16	100
46	C	-	E15	117	62	D	-	B15	101
47	C	-	-	-	63	D	-	-	-
48	C	31	F16	118	64	D	41	A17	102

Table 18. EPM7256E I/O Pin-Outs (Part 2 of 4)

MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP	MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP
65	E	153	U12	168	81	F	21	J16	130
66	E	—	—	—	82	F	—	—	—
67	E	152	R13	169	83	F	20	J15	131
68	E	—	—	—	84	F	—	—	—
69	E	151	U11	170	85	F	19	K17	132
70	E	—	T13	171	86	F	—	J14	133
71	E	—	—	—	87	F	—	—	—
72	E	150	T11	172	88	F	17	K16	135
73	E	149	T12	173	89	F	16	K15	136
74	E	—	—	—	90	F	—	—	—
75	E	147	R12	175	91	F	15	L17	137
76	E	—	—	—	92	F	—	—	—
77	E	146	U10	176	93	F	14	L16	138
78	E	—	R10	177	94	F	—	M17	139
79	E	—	—	—	95	F	—	—	—
80	E	145	T10	178	96	F	13	L15	140
97	G	30	E16	119	113	H	60	C9	79
98	G	—	—	—	114	H	—	—	—
99	G	29	F17	120	115	H	59	D9	80
100	G	—	—	—	116	H	—	—	—
101	G	28	F15	121	117	H	58	C10	81
102	G	—	G16	122	118	H	—	A10	84
103	G	—	—	—	119	H	—	—	—
104	G	27	G15	123	120	H	54	A11	86
105	G	26	G17	124	121	H	53	B10	87
106	G	—	—	—	122	H	—	—	—
107	G	24	H17	126	123	H	52	A12	88
108	G	—	—	—	124	H	—	—	—
109	G	23	H15	127	125	H	51	B11	89
110	G	—	J17	128	126	H	—	A13	90
111	G	—	—	—	127	H	—	—	—
112	G	22	H16	129	128	H	50	C12	91

Table 18. EPM7256E I/O Pin-Outs (Part 3 of 4)

MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP	MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP
129	I	128	U6	197	145	J	100	J2	27
130	I	—	—	—	146	J	—	—	—
131	I	129	T5	196	147	J	101	J3	26
132	I	—	—	—	148	J	—	—	—
133	I	130	U7	195	149	J	102	K1	25
134	I	—	T6	194	150	J	—	J4	24
135	I	—	—	—	151	J	—	—	—
136	I	131	T7	193	152	J	104	K2	22
137	I	132	R6	192	153	J	105	K3	21
138	I	—	—	—	154	J	—	—	—
139	I	134	R7	190	155	J	106	L1	20
140	I	—	—	—	156	J	—	—	—
141	I	135	U8	189	157	J	107	L2	19
142	I	—	R8	188	158	J	—	M1	18
143	I	—	—	—	159	J	—	—	—
144	I	136	T8	187	160	J	108	L3	17
161	K	91	F3	38	177	L	61	B9	78
162	K	—	—	—	178	L	—	—	—
163	K	92	F1	37	179	L	62	C8	77
164	K	—	—	—	180	L	—	—	—
165	K	93	E2	36	181	L	63	A9	76
166	K	—	G2	35	182	L	—	A8	73
167	K	—	—	—	183	L	—	—	—
168	K	94	G3	34	184	L	67	A7	71
169	K	95	G1	33	185	L	68	B8	70
170	K	—	—	—	186	L	—	—	—
171	K	97	H1	31	187	L	69	A6	69
172	K	—	—	—	188	L	—	—	—
173	K	98	H3	30	189	L	70	B7	68
174	K	—	J1	29	190	L	—	A5	67
175	K	—	—	—	191	L	—	—	—
176	K	99	H2	28	192	L	71	C6	66



Table 18. EPM7256E I/O Pin-Outs (Part 4 of 4)

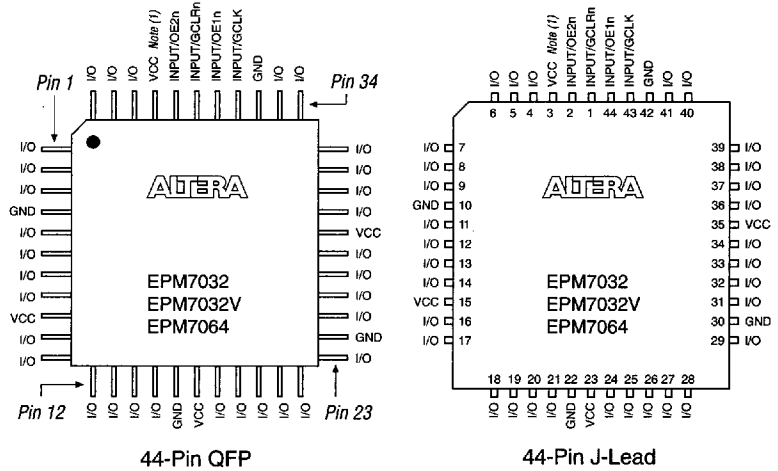
MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP	MC	LAB	160-Pin QFP	192-Pin PGA	208-Pin QFP
193	M	119	U1	4	209	N	109	N1	16
194	M	–	–	–	210	N	–	–	–
195	M	120	R2	3	211	N	110	M2	15
196	M	–	–	–	212	N	–	–	–
197	M	121	R3	206	213	N	112	M3	13
198	M	–	U2	205	214	N	–	P1	12
199	M	–	–	–	215	N	–	–	–
200	M	122	P4	204	216	N	113	N2	11
201	M	123	U3	203	217	N	114	R1	10
202	M	–	–	–	218	N	–	–	–
203	M	124	T3	202	219	N	115	P2	9
204	M	–	–	–	220	N	–	–	–
205	M	125	U4	201	221	N	116	T1	8
206	M	–	U5	199	222	N	–	N3	7
207	M	–	–	–	223	N	–	–	–
208	M	127	T4	198	224	N	117	T2	6
225	O	82	B1	49	241	P	72	A4	65
226	O	–	–	–	242	P	–	–	–
227	O	83	C3	48	243	P	73	B6	64
228	O	–	–	–	244	P	–	–	–
229	O	84	C1	47	245	P	75	B5	62
230	O	–	D3	46	246	P	–	A3	61
231	O	–	–	–	247	P	–	–	–
232	O	85	D1	45	248	P	76	B4	60
233	O	86	C2	44	249	P	77	A2	59
234	O	–	–	–	250	P	–	–	–
235	O	87	E1	43	251	P	78	C4	58
236	O	–	–	–	252	P	–	–	–
237	O	88	E3	42	253	P	79	B2	57
238	O	–	D2	40	254	P	–	B3	56
239	O	–	–	–	255	P	–	–	–
240	O	90	F2	39	256	P	80	A1	55

# Pin-Out Diagrams

Figures 17 through 22 show the package pin-out diagrams of MAX 7000 devices.

**Figure 17. 44-Pin Package Pin-Out Diagram**

Package outlines not drawn to scale.



**Note:**

(1) Pin 41 is a power-down pin (PDn) for the EMP7032V device.

**Figure 18. 68-Pin Package Pin-Out Diagram**

Package outline not drawn to scale.

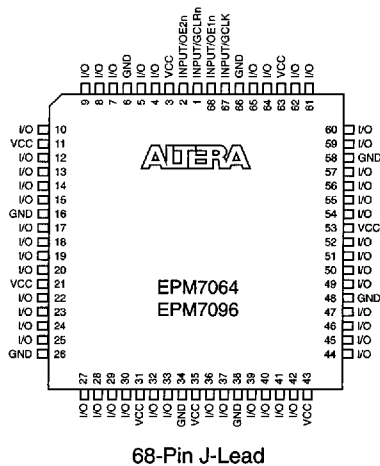
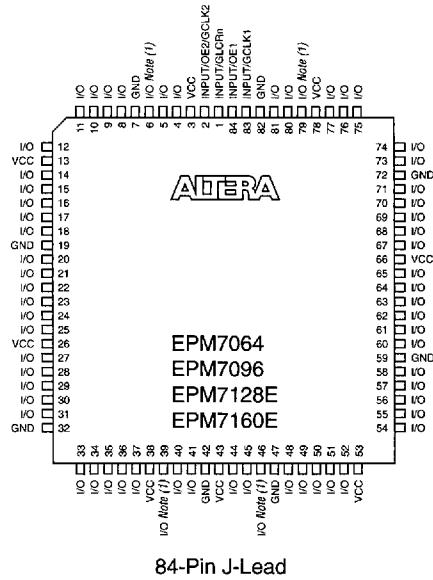


Figure 19. 84-Pin Package Pin-Out Diagram

Package outline not drawn to scale.



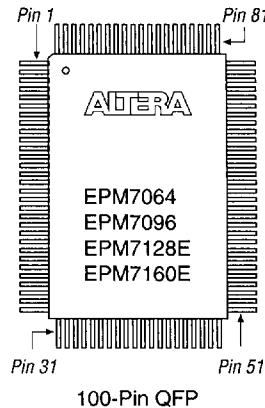
84-Pin J-Lead

Note:

- (1) Pins 6, 39, 46, and 79 are no-connect (N.C.) pins on EPM7096 and EPM7160E devices.

Figure 20. 100-Pin Package Pin-Out Diagram

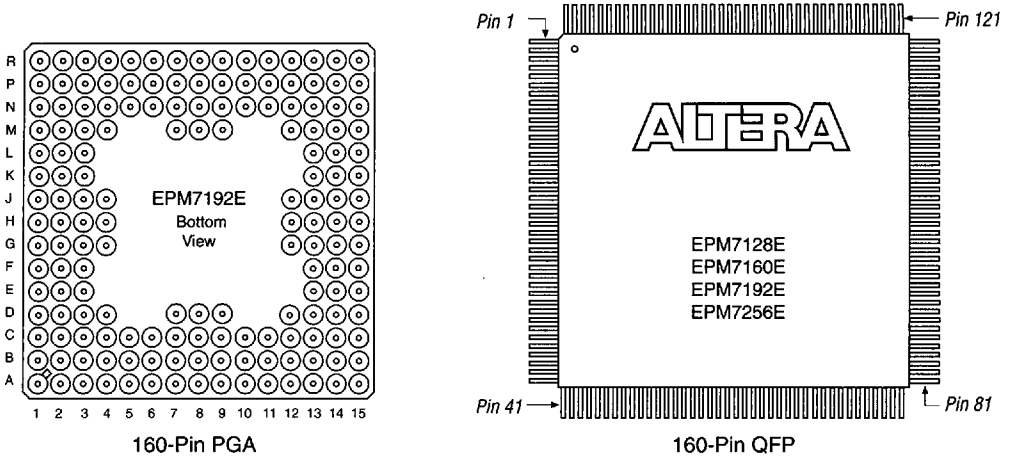
Package outline not drawn to scale.



100-Pin QFP

**Figure 21. 160-Pin Package Pin-Out Diagram.**

Package outline not drawn to scale.



**Figure 22. 192-Pin Package Pin-Out Diagram**

Package outline not drawn to scale.

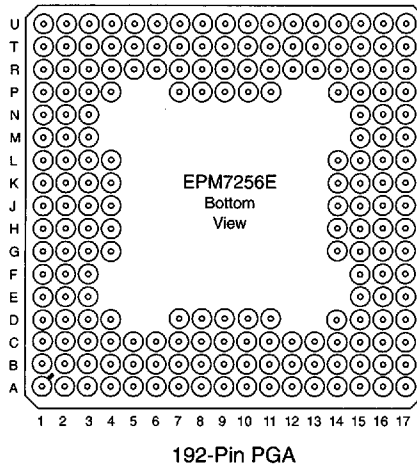


Figure 23. 208-Pin Package Pin-Out Diagram

Package outline not drawn to scale.

